

6 I/O 8-bit MTP-Based MCU with EEPROM

**Version 1.1** 

Mar. 25, 2020

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### **Revision History**

Version	Date	Description	Modified Page
1.0	2019/05/31	Formal release.	-
1.1	2020/03/25	Add OSC Characterstics.	78









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NY8AE51D

### 1. 概述

NY8AE51D是以MTP作為程式記憶體,並以EEPROM作為資料記憶體的 8 位元微控制器,特別適合斷電後還需保持 資料內容的IO產品的應用,例如遙控器、風扇/燈光控制或是遊樂器周邊等等。而MTP作為程式記憶體能更方便且有 效率的開發產品。NY8AE51D核心建立在RISC精簡指令集架構可以很容易地做編輯和控制,共有 60 條指令。除了少 數指令需要 2 個時序,大多數指令都是 1 個時序即能完成,可以讓使用者輕鬆地以程式控制完成不同的應用。因此非 常適合各種中低記憶容量但又複雜的應用。

在I/O的資源方面,NY8AE51D有 6 根彈性的雙向I/O腳,每個I/O腳都有單獨的暫存器控制為輸入或輸出腳。而且每一 個I/O腳位都有附加的程式控制功能如上拉或下拉電阻或開漏極(Open-Drain)輸出。此外針對紅外線搖控的產品方 面,NY8AE51D內建了可選擇頻率的紅外載波發射口。

NY8AE51D有兩組計時器,可用系統頻率當作一般的計時的應用或者從外部訊號觸發來計數。另外NY8AE51D提供3 組 10 位元解析度的PWM輸出及一組蜂鳴器輸出,可用來驅動馬達、LED、或蜂鳴器等等。

NY8AE51D採用雙時鐘機制,高速振盪或者低速振盪都由內部RC振盪輸入。在雙時鐘機制下,NY8AE51D可選擇多 種工作模式如正常模式(Normal)、慢速模式(Slow mode)、待機模式(Standby mode) 與睡眠模式(Halt mode)可節省 電力消耗延長電池壽命。

在省電的模式下如待機模式(Standby mode)與睡眠模式(Halt mode)中,有多種事件可以觸發中斷喚醒NY8AE51D進 入正常操作模式(Normal) 或 慢速模式(Slow mode) 來處理突發事件。

#### 1.1 功能

- 寬廣的工作電壓: (指令週期為 4 個CPU clock, 亦即 4T模式)
  - 2.4V~5.5V @系統頻率≦8MHz。
- 寬廣的工作温度: -40°C~85°C。
- 1Kx14 bits MTP
- 64 bytes SRAM
- 64 bytes EEPROM
- 6 根可分別單獨控制輸入輸出方向的I/O腳(GPIO)、PB[5:0]。
- ▶ PB[3:0]可選擇輸入時使用內建下拉電阻。
- PB[5:0]可選擇上拉電阻或開漏極輸出(Open-Drain)。
- 8 層程式堆棧(Stack)。
- 存取資料有直接或間接定址模式。
- 一組 8 位元上數計時器(Timer0)包含可程式化的頻率預除線路。
- 一組 10 位元下數計時器(Timer1)可選重複載入或連續下數計時。
- 三個 10 位元的脈衝寬度調變輸出(PWM1/2/3)。



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- 一個蜂鳴器輸出(BZ1)。
- 38/57KHz紅外線載波頻率可供選擇,同時載波之極性也可以根據數據作選擇。
- 內建上電復位電路(POR)。
- 內建低壓復位功能(LVR)。
- 內建 16.段低電壓偵測功能(LVD)。
- 內建看門狗計時(WDT),可由程式韌體控制開關。
- 雙時鐘機制,系統可以隨時切換高速振盪或者低速振盪。
  - 高速振盪: I HRC (1~20MHz內部高速RC振盪)
  - 低速振盪: I\_LRC (內部 32KHz低速RC振盪)
- 四種工作模式可隨系統需求調整電流消耗:正常模式(Normal)、慢速模式(Slow mode)、待機模式(Standby mode) 與 睡眠模式(Halt mode)。

- 七種硬體中斷:
  - Timer0 溢位中斷。
  - Timer1 借位中斷。
  - WDT 中斷。
  - PB 輸入狀態改變中斷
  - 外部中斷輸入。
  - 低電壓偵測中斷。
  - EEPROM寫入完成中斷
- NY8AE51D在待機模式(Standby mode)下的六種喚醒中斷:
  - Timer0 溢位中斷。
  - Timer1 借位中斷。
  - WDT\_中斷。
  - PB 輸入狀態改變中斷
  - 外部中斷輸入。
  - 低電壓偵測中斷。
- NY8AE51D在睡眠模式(Halt mode)下的三種喚醒中斷:
  - WDT 中斷。
  - PB 輸入狀態改變中斷。
  - 外部中斷輸入。
- NY8AE51D提供兩種電流檔位(Small / Normal)



### 1. General Description

NY8AE51D is a MTP/EEPROM based 8-bit MCU tailored for I/O based applications like remote controllers, fan/light controller, game controllers, toy and various controllers. The MTP offers the advantage of convenient and effective way of developing user program. The EEPROM, unlike SRAM, features data retention after IC is powered off. NY8AE51D adopts advanced CMOS technology to provide customers remarkable solution with low cost and high performance benefits. RISC architecture is applied to NY8AE51D and it provides 53 instructions. All instructions are executed in single instruction cycle except program branch and skip instructions which will take two instruction cycles. Therefore, NY8AE51D is very suitable for those applications that are sophisticated but compact program size is required.

As NY8AE51D address I/O type applications, it can provide 6 I/O pins for applications which require abundant input and output functionality. Moreover, each I/O pin may have additional features, like Pull-High/Pull-Low resistor and open-drain output type through programming. Moreover, NY8AE51D has built-in infrared (IR) carrier generator with selectable IR carrier frequency and polarity for applications which demand remote control feature.

NY8AE51D also provides 2 sets of timers which can be used as regular timer based on system oscillation or event counter with external trigger clock. Moreover, NY8AE51D provides 3 set of 10-bit resolution Pulse Width Modulation (PWM1/2/3) output and 1 set buzzer output in order to drive motor/LED and buzzer.

NY8AE51D employs dual-clock oscillation mechanism, both high oscillation or low oscillation can be derived from internal resistor/capacitor oscillator. Moreover, based on dual-clock mechanism, NY8AE51D provides kinds of operation mode like Normal mode, Slow mode, Standby mode and Halt mode in order to save power consumption and lengthen battery operation life.

While NY8AE51D operates in Standby mode and Halt mode, kinds of event will issue interrupt requests and can wake-up NY8AE51D to enter Normal mode and Slow mode in order to process urgent events.

#### 1.1 Features

- Wide operating voltage range: (@ 4 CPU clock per instruction, i.e. 4T mode)
  - 2.4V ~ 5.5V @system clock ≤8MHz.
- Wide operating temperature: -40°C ~ 85°C.
- 1K x 14 bits MTP.
- 64 bytes SRAM.
- 64 bytes EEPROM.
- 6 general purpose I/O pins (GPIO), PB[5:0], with independent direction control.
- PB[3:0] have features of Pull-Low resistor for input pin.
- PB[5:0] have features of Pull-High resistor, and open-drain output.
- 8-level hardware Stack.

# 5

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- Direct and indirect addressing modes for data access.
- One 8-bit up-count timer (Timer0) with programmable prescaler.
- One 10-bit reload or continuous down-count timers (Timer1).
- Three 10-bit resolution PWM (PWM1/2/3) output.
- One buzzer (BZ1) output.
- Selectable 38/57KHz IR carrier frequency and high/low polarity according to data value.
- Built-in Power-On Reset (POR).
- Built-in high-precision Low-voltage detector(LVD) .
- Built-in Low-Voltage Reset (LVR).
- Built-in 16-segment Low-Voltage Detect (LVD).
- Built-in Watch-Dog Timer (WDT) enabled/disabled by firmware control.
- Dual-clock oscillation: System clock can switch between high oscillation and low oscillation.
  - High oscillation: I\_HRC (Internal High Resistor/Capacitor Oscillator ranging from 1M~20MHz)
  - Low oscillation: I\_LRC (Internal 32KHz oscillator)
- Four kinds of operation mode to reduce system power consumption:
  - · Normal mode, Slow mode, Standby mode and Halt mode.
- Seven hardware interrupt events:
  - Timer0 overflow interrupt.
  - Timer1 underflow interrupt.
  - WDT timeout interrupt.
  - PB input change interrupt.
  - External interrupt.
  - LVD interrupt.
  - · End of EEPROM write interrupt.
- Six interrupt events to wake-up NY8AE51D from Standby mode:
  - Timer0 overflow interrupt.
  - · Timer1 underflow interrupt.
  - WDT timeout interrupt.
  - · PB input change interrupt.
  - External interrupt.
  - · LVD interrupt.
- Three interrupt events to wake-up NY8AE51D from Halt mode:
  - · WDT timeout interrupt.
  - PB input change interrupt.
  - External interrupt.
- There are two current options (Small / Normal )can be selected.

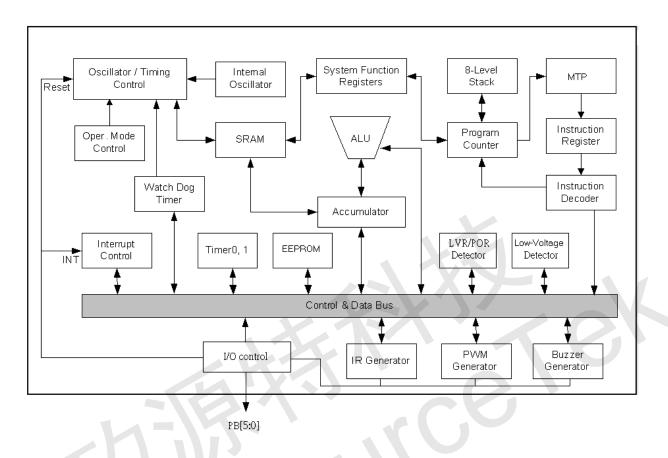


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### 1.2 Block Diagram



### 1.3 Pin Assignment

NY8AE51D provides three kinds of package type which are SOP8 and SOT23-6.



Figure 1 Package pin assignment



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### 1.4 Pin Description

Pin Name	I/O	Description
PB0/ INT/ PWM2 / SDA	I/O	PB0 is a bidirectional I/O pin. PB0 is input pin of external interrupt when EIS=1 & INTIE=1. PB0 can be PWM2 output. PB0 can be programming pad SDA.
PB1/ IR /PWM3	I/O	PB1 is a bidirectional I/O pin. If IR mode is enabled, this pin is IR carrier output. PB1 can be PWM3 output.
PB2 / EX_CKI / PWM1 / BZ1 / SCL	I/O	PB2 is a bidirectional I/O pin. It can also be timer clock source EX_CKI. It can also be PWM1 output. It can also be BUZZER1 output. PB2 can be programming pad SCL.
PB3/ RSTb	I/O	PB3 is a bidirectional I/O pin. It can be reset pin RSTb. If RSTb pin is low, it will reset NY8AE51D.
PB4	I/O	PB4 is a bidirectional I/O pin. PB4 also can be output of instruction clock.
PB5	I/O	PB5 is a bidirectional I/O pin.
VDD		Positive power supply.
VSS	-	Ground.



### 2. Memory Organization

NY8AE51D memory is divided into two categories: one is program memory and the other is data memory. Data memory is sub-divided into SRAM/Register Memory and EEPROM Memory.

#### 2.1 **Program Memory**

The program memory space of NY8AE51D is 1K words. Therefore, the Program Counter (PC) is 10-bit wide in order to address any location of program memory.

Some locations of program memory are reserved as interrupt entrance. Power-On Reset vector is located at 0x000. Software interrupt vector is located at 0x001. Internal and external hardware interrupt vector is located at 0x008.

NY8AE51D provides instruction GOTOA, CALLA to address 256 location of program space. NY8AE51D also provides instructions LCALL and LGOTO to address any location of program space.

When a call or interrupt is happening, next ROM address is written to top of the stack, when RET, RETIA or RETIE instruction is executed, the top of stack data is read and load to PC.

NY8AE51D program ROM address 0x3FE~0x3FF are reserved space, if user tries to write code in these addresses will get unexpected false functions.

NY8AE51D program ROM address 0x00E~0x00F are preset rolling code can be released and used as normal program space.

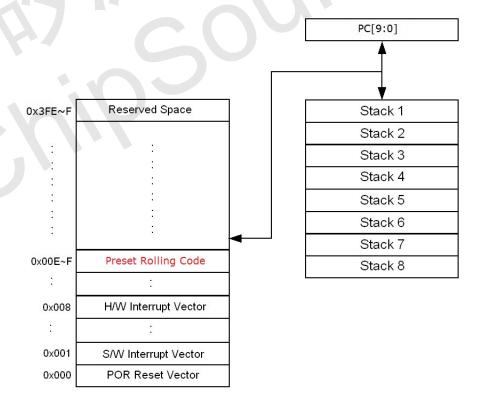


Figure 2 Program Memory Address Mapping

TEL: +86-0755-27595155 27595165 FAX: +86-0755-27594792 WEB:Http://www.ChipSourceTek.com E-mail: Sales@ChipSourceTek.com



#### 2.2 **SRAM/Register Memory**

According to instructions used to access SRAM/register memory, the memory can be divided into three kinds of categories: one is R-page Special-function Register (SFR) + General Purpose Register (GPR), another is F-page SFR and the other is S-page SFR. GPR are made of SRAM and user can use them to store variables or intermediate results.

R-page data memory is divided into 4 banks and can be accessed directly or indirectly through a SFR register which is File Select Register (FSR). STATUS[7:6] are used as Bank register BK[1:0] to select one bank out of the 4 banks.

R-page register can be divided into addressing mode: direct addressing mode and indirect addressing mode.

The indirect addressing mode of data memory access is described in the following graph. This indirect addressing mode is implied by accessing register INDF. The bank selection is determined by STATUS[7:6] and the location selection is from FSR[6:0].

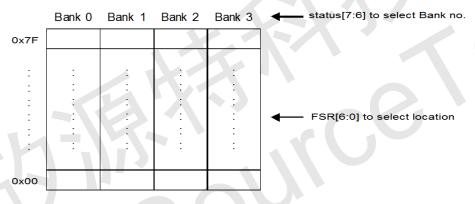
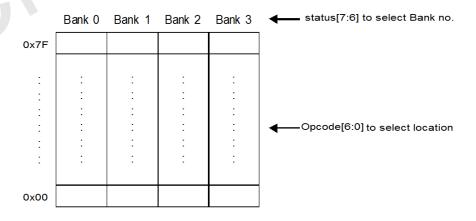


Figure 3 Indirect Addressing Mode of Data Memory Access

The direct addressing mode of data memory access is described below. The bank selection is determined by STATUS[7:6] and the location selection is from instruction op-code[6:0] immediately.



Direct Addressing Mode of Data Memory Access



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R-page SFR can be accessed by general instructions like arithmetic instructions and data movement instructions. The R-page SFR occupy address from 0x0 to 0x1F of Bank 0. However, the same address range of Bank 1, Bank 2 and Bank 3 are mapped back to Bank 0. In other words, R-page SFR physically existed at Bank 0. The GPR physically occupy address from 0x20 to 0x5F of Bank and other banks in address from 0x20 to 0x5F are mapped back as the Table 1 shows.

The NY8AE51D register name and address mapping of R-page SFR are described in the following table.

FSR[7:6]	00	01	10	11
Address	(Bank 0)	(Bank 1)	(Bank 2)	(Bank 3)
0x0	INDF			
0x1	TMR0			
0x2	PCL			
0x3	STATUS			
0x4	FSR			
0x5	-	X 77		
0x6	PORTB	-3-11		
0x7	1-			
0x8	PCON			
0x9	BWUCON			
0xA	PCHBUF			
0xB	BPLCON	The	same mapping as Ba	ank 0
0xC	BPHCON		oamo mapping ao Bo	
0xD				
0xE	INTE			
0xF	INTF			
0x10 ~ 0x16	-			
0x17	INTE2			
0x18	INTEDG			
0x19	TMRH			
0x1A ~ 0x1B	-			
0x1C	PWM3RH			
0x1D ~ 0x1E	-			
0x1F	INTF2			
0x20 ~ 0x5F	General Purpose Register	The	same mapping as Ba	ank 0

Table 1 R-page SFR Address Mapping



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F-page SFR can be accessed only by instructions IOST and IOSTR. S-page SFR can be accessed only by instructions SFUN and SFUNR. STATUS[7:6] bank select bits are ignored while F-page and S-page register is accessed. The register name and address mapping of F-page and S-page are depicted in the following table.

SFR Category Address	F-page SFR	S-page SFR
0x0	-	TMR1
0x1	-	T1CR1
0x2	-	T1CR2
0x3	-	PWM1DUTY
0x4	-	PS1CV
0x5	-	BZ1CR
0x6	IOSTB	IRCR
0x7	-	TBHP
0x8	-	TBHD
0x9	-	1
0xA	PS0CV	P2CR1
0xB	13-X	-
0xC	BODCON	PWM2DUTY
0xD ~ 0xE	113	-
0xF	PCON1	OSCCR
0x10	-	
0x11	-	P3CR1
0x12		-
0x13	-	PWM3DUTY

Table 2 F-page and S-page SFR Address Mapping

#### 2.3 **EEPROM Memory**

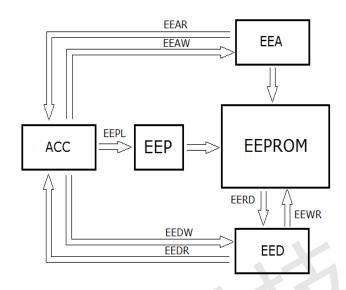
Read and write access to EEPROM memory take place indirectly through 3 special function registers, namely, EEA, EED and EEP. EEA register holds the EEPROM address to be access. EED register holds the data to be written, or the data read at the address in EEA. EEP holds the unlock key to write EEPROM data. The following figure shows the block diagram how EEPROM operates.



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NY8AE51D provides 7 instructions to control the data flow between these 3 special register and 64-byte EEPROM. EEAR/EEAW read/write the EEA register. EEDR/EEDW read/write the EED register. EERD/EEWR /EEPL instructions, on the other hand, control the data path between EEPROM and EED register, according to the EEPROM address provided by EEA. The following table describes the EEPROM instructions.

Mnemonic Operands	Description	Status affected
EEAR	Read EEA to ACC	-
EEAW	Write EEA from ACC	-
EEDR	Read EED to ACC	-
EEDW	Write EED from ACC	-
EERD	Read EEPROM(EEA),and wite to EED	
EERD	register	ACC is unknown
EEWR	Write EEPROM(EEA) with data from	
LEWK	EED register	-
EEPL	Write serial codes to unlock EE write	
EEFL	protect	-

Before writing EEPROM data with the EEWR instruction, 3 consecutive code must be written to the EEP register with the EEPL instruction. These 3 code are C9H, 3AH and D3H. After these 3 code are written to EEP register, the EEPROM write protection is unlocked and data will be written to EEPROM by applying the EEWR instruction. The following are example code of EEPROM write unlock process.

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**MOVIA** C9H

**EEPL** 

**MOVIA** 3AH

**EEPL** 

**MOVIA** D<sub>3</sub>H







**EEPL FFWR** 

When EEWR is successfully executed and completed, an EEWIF interrupt will be launched if the EEWIE is set to 1 and the global interrupt GIE is enabled.

#### Note:

- 1. NY8AE51D EEPROM writing actions can only be done in normal mode, it is not guaranteed in slow mode. If NY8AE51D is in slow mode, please switch to normal mode before EEPROM write operations.
- 2. To prevent unwanted halt in a running program if EEPROM writes fail, enabling the watchdog reset is suggested.
- 3. When user writes data to EEPROM, it's suggested to turn on LVD = 2.4V function to monitor VDD.
- 4. When VDD is under 2.4v, data cannot be written into EEPROM. User can use LVD & LVR function to prevent writing data to EEPROM Fail.

### 2.3.1 EEA (EEPROM Address Register)

Name SFR Type		Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
EEA EE		X	EEA[6:0]						
R/W F	Property	Х		R/W					
Initia	l Value	X				XXXXX	Х		

EEA[6:0]: Point to EEPROM address. EEA[6] must be 0. Read/Write this register by instruction EEAR/EEAW.

### **EED (EEPROM Data Register)**

Name	SFR Type	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
EED	EE	EED[7:0]							
R/W I	Property	R/W							
Initia	al Value	xxxxxxxx							

**EED[7:0]:** EEPROM data register . Read/Write this register by instruction EEDR/EEDW.



### 3. Function Description

This chapter will describe the detailed operations of NY8AE51D.

### 3.1 R-page Special Function Register

#### 3.1.1 **INDF** (Indirect Addressing Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0					
INDF	R	0x0	INDF[7:0]							INDF[7:0]					
	R/W Propert	R/W													
	Initial Value				XXXX	XXXX									

The register INDF is not physically existed and it is used as indirect addressing mode. Any instruction accessing INDF actually accesses the register pointed by register FSR

#### TMR0 (Timer0 Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TMR0	R	0x1				TMR	0[7:0]			
	R/W Property					R	W			
	Initial Value					XXXX	XXXX			

When read the register TMR0, it actually read the current running value of Timer0.

Write the register TMR0 will change the current value of Timer0.

Timer0 clock source can be from instruction clock F<sub>INST</sub> or from external pin EX\_CKI, or from Low Oscillator Frequency according to T0MD and configuration word setting.

### 3.1.3 PCL (Low Byte of PC[9:0])

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PCL	R	0x2				PCL	[7:0]			
	R/W Property					R	W			
	Initial Value		0x00							

The register PCL is the least significant byte (LSB) of 10-bit PC. PCL will be increased by one after one instruction is executed except some instructions which will change PC directly. The high byte of PC, i.e. PC[9:8], is not directly accessible. Update of PC[9:8] must be done through register PCHBUF.

For LGOTO instruction, PC[9:0] is from instruction word.

For LCALL instruction, PC[9:0] is from instruction word. Moreover the next PC address, i.e. PC+1, will push onto top of Stack.



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### 3.1.4 STATUS (Status Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
STATUS	R	0x3	BK[1]	BK[0]	GP5	/TO	/PD	Z	DC	O
R	/W Property		R/W	R/W	R/W	R/W(*2)	R/W(*1)	R/W	R/W	R/W
I	nitial Value		0	0	0	1	1	Χ	Х	Х

The register STATUS contains result of arithmetic instructions and reasons to cause reset.

C: Carry/Borrow bit

C=1, carry is occurred for addition instruction or borrow is not occurred for subtraction instruction.

C=0, carry is not occurred for addition instruction or borrow is occurred for subtraction instruction.

DC: Half Carry/half Borrow bit

DC=1, carry from the 4th LSB is occurred for addition instruction or borrow from the 4th LSB is not occurred for subtraction instruction.

DC=0, carry from the 4th LSB is not occurred for addition instruction or borrow from the 4th LSB is occurred for subtraction instruction.

Z: Zero bit

Z=1, result of logical operation is zero.

Z=0, result of logical operation is not zero.

/PD: Power down flag bit

/PD=1, after power-up or after instruction CLRWDT is executed.

/PD=0, after instruction SLEEP is executed.

/TO: Time overflow flag bit

/TO=1, after power-up or after instruction CLRWDT or SLEEP is executed.

/TO=0, WDT timeout is occurred.

**BK[1:0]:** Bank register, used to select one specific bank of data ram/register.

GP5: General read/write register bits.

(\*1) can be cleared by sleep instruction.

(\*2) can be set by CLRWDT instruction.

#### 3.1.5 FSR (Register File Selection Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
FSR	R	0x4	GP7	FSR[6:0]						
	R/W Property		R/W				R/W			
	Initial Value		0	X X X X X X X						Х

FSR[6:0]: Select one register out of 128 registers of specific Bank.

GP7: General read/write register bits.

TEL: +86-0755-27595155 27595165 FAX: +86-0755-27594792 WEB:Http://www.ChipSourceTek.com E-mail: Sales@ChipSourceTek.com



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### 3.1.6 PortB (PortB Data Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PortB	R	0x6	GP7	GP6	PB5	PB4	PB3	PB2	PB1	PB0
	R/W Propert	ty				R	W			
	Initial Value	;	Data la	atch value	e is xxxxx	x, read va	lue is xxx	xxx port	value(PB	5~PB0)

While reading PortB, it will get the status of the specific pin if that pin is configured as input pin. However, if that pin is configured as output pin, whether it will get the status of the pin or the value of the corresponding output data latch is depend on the configuration word RD OPT. While writing to PortB, data is written to PB's output data latch.

GP7, GP6: General purpose read/write register bit.

### **PCON (Power Control Register)**

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PCON	R	0x8	WDTEN	GP6	LVDEN	GP4	LVREN	GP2	GP1	EELOCK
F	R/W Property	•			, N	R/W				R
	Initial Value		1	0	0	0	1	0	0	1

GP6,4,2,1: General read/write register bits.

LVREN: Enable/disable LVR.

LVREN=1, enable LVR.

LVREN=0, disable LVR.

WDTEN: Enable/disable WDT.

WDTEN=1, enable WDT.

WDTEN=0, disable WDT.

LVDEN: Enable/disable LVD.

LVDEN=1, enable LVD.

LVDEN=0, disable LVD.

**EELOCK:** Check EEPORM write lock state bit.

EELOCK=1, EEPROM Write function is locked.

EELOCK=0, EEPROM Write function is unlocked.

TEL: +86-0755-27595155 27595165 FAX: +86-0755-27594792 WEB:Http://www.ChipSourceTek.com E-mail: Sales@ChipSourceTek.com Ver. 1.1 2020/03/25



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### 3.1.8 BWUCON (PortB Wake-up Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BWUCON	R	0x9	-	-	WUPB5	WUPB4	WUPB3	WUPB2	WUPB1	WUPB0
R/W	Property	/	-	-	R/W	R/W	R/W	R/W	R/W	R/W
Initi	al Value	•	Х	Х	1	1	1	1	1	1

**WUPBx:** Enable/disable PBx wake-up function,  $0 \le x \le 5$ .

WUPBx=1, enable PBx wake-up function.

WUPBx=0, disable PBx wake-up function.

### 3.1.9 PCHBUF (High Byte of PC)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PCHBUF	R	0xA	GP7	-	,	-	-		PCHE	BUF[1:0]
R/	W Property		R/W	-	-		-	-	F	R/W
Ir	itial Value		0	X	X	X	Х	Х		00

PCHBUF[1:0]: Buffer of the 9<sup>th</sup> bit, 8<sup>th</sup> bit of PC.

GP7: General read/write register bit.

### 3.1.10 BPLCON (PortB Pull-Low Resistor Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BPLCON	R	0xB	/PLPB3	/PLPB2	/PLPB1	/PLPB0	ı	ı	ı	ı
RΛ	V Propert	y	R/W	R/W	R/W	R/W	-	-	-	-
In	itial Value		1	1	1	1	Х	Х	Х	Х

**/PLPBx:** Disable/enable PBx Pull-Low resistor,  $0 \le x \le 3$ .

/PLPBx=1, disable PBx Pull-Low resistor.

/PLPBx=0, enable PBx Pull-Low resistor.

### 3.1.11 BPHCON (PortB Pull-High Resistor Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BPHCON	R	0xC	1	ı	/PHPB5	/PHPB4	/PHPB3	/PHPB2	/PHPB1	/PHPB0
R/W	Propert	У	-	-	R/W	R/W	R/W	R/W	R/W	R/W
Initi	al Value	}	Х	Х	1	1	1	1	1	1

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/PHPBx: Disable/enable PBx Pull-High resistor,  $0 \le x \le 5$ .

/PHPBx=1, disable PBx Pull-High resistor.

/PHPBx=0, enable PBx Pull-High resistor.







### 3.1.12 INTE (Interrupt Enable Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTE	R	0xE	-	WDTIE	-	LVDIE	T1IE	INTIE	PBIE	T0IE
R/	W Proper	ty	-	R/W	-	R/W	R/W	R/W	R/W	R/W
Ir	nitial Value	е	Х	0	Х	0	0	0	0	0

**T0IE:** Timer0 overflow interrupt enable bit.

T0IE=1, enable Timer0 overflow interrupt.

T0IE=0, disable Timer0 overflow interrupt.

PBIE: PortB input change interrupt enable bit.

PBIE=1, enable PortB input change interrupt.

PBIE=0, disable PortB input change interrupt.

INTIE: External interrupt enable bit.

INTIE=1, enable external interrupt.

INTIE=0, disable external interrupt.

T1IE: Timer1 underflow interrupt enable bit.

T1IE=1, enable Timer1 underflow interrupt.

T1IE=0, disable Timer1 underflow interrupt.

**WDTIE:** WDT timeout interrupt enable bit.

WDTIE=1, enable WDT timeout interrupt.

WDTIE=0, disable WDT timeout interrupt.

LVDIE: Low-voltage detector interrupt enable bit.

LVDIE=1, enable low-voltage detector interrupt.

LVDIE=0, disable low-voltage detector interrupt.

### 3.1.13 INTF (Interrupt Flag Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTF	R	0xF	-	WDTIF	-	LVDIF	T1IF	INTIF	PBIF	T0IF
	R/W Propert	ty	-	R/W	-	R/W	R/W	R/W	R/W	R/W
In	itial Value(no	te*)	Х	0	Х	0	0	0	0	0

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T0IF: Timer0 overflow interrupt flag bit.

T0IF=1, Timer0 overflow interrupt is occurred.

T0IF must be clear by firmware.

PBIF: PortB input change interrupt flag bit.

PBIF=1, PortB input change interrupt is occurred.

PBIF must be clear by firmware.

**INTIF:** External interrupt flag bit.



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INTIF=1, external interrupt is occurred.

INTIF must be clear by firmware.

T1IF: Timer1 underflow interrupt flag bit.

T1IF=1, Timer1 underflow interrupt is occurred.

T1IF must be clear by firmware.

WDTIF: WDT timeout interrupt flag bit.

WDTIF=1, WDT timeout interrupt is occurred.

WDTIF must be clear by firmware.

LVDIF: Low-voltage detector interrupt flag bit.

LVDIF=1, Low-voltage detector interrupt is occurred.

LVDIF must be clear by firmware.

Note: When corresponding INTE bit is not enabled, the read interrupt flag is 0.

### 3.1.14 INTE2 (Interrupt enable Register 2)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTE2	R	0x17	-	-	-	EEWIE		-	-	-
R	-	-	-	R/W	-	<b>J</b> -	-	-		
l	Initial Value				Х	0	X	Х	Х	Х

**EEWIE**: EEPROM write completion interrupt enable.

EEWIE=1, enable EEPROM write completion interrupt.

EEWIE=0, disable EEPROM write completion interrupt.

### 3.1.15 INTEDG (Interrupt Edge Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTEDG	R	0x18	-	-	-	EIS	-	-	INTG1	INTG0
R	R/W Property		-	-	-	R/W	-	-	R/W	R/W
Initial Value			Х	Х	Х	0	Х	Х	0	1

**EIS:** External interrupt select bit

EIS=1, PB0 is external interrupt.

EIS=0, PB0 is GPIO.

INTG1~0: INT edge trigger select bit.

00: reserved, 01: rising edge, 10: falling edge, 11: rising/falling edge.



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### 3.1.16 TMRH (Timer High Byte Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TMRH	R	0x19	ı	ı	TMR19	TMR18	PWM2 DUTY9	PWM2 DUTY8	PWM1 DUTY9	PWM1 DUTY8
R/W	/ Proper	ty	ı	ı	R/W	R/W	R/W	R/W	R/W	R/W
Init	ial Valu	е	Х	Х	Х	Х	Х	Х	Х	X

TMR19~8: Timer1 MSB 2 bits. Write these 2 bits will overwrite the 10-bit Timer1 load value of bit 9 and 8. Read these 2 bits will get the Timer1 bit9-8 current value.

PWM1DUTY9~8: PWM1 duty data MSB 2 bits.

PWM2DUTY9~8: PWM2 duty data MSB 2 bits.

#### Note

- 1. TRMH Initial Value is unknown, user needs to write initial data before use it.
- 2. TMRH can't be used BSR / BCR instruction to modify. Because these instructions are read-modify-write commands, user will get the current value of timer by reading TMR19 / **TMR18.**

### 3.1.17 PWM3RH (PWM3DUTY High Byte Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PWM3RH	R	0x1C	1	-	1	1	1	ı	PWM3DUTY9	PWM3DUTY8
R/\	W Property		-	-	-	, (	-	1	R/W	R/W
In	itial Value		X	Х	X	Х	Х	Х	Х	Х

PWM3DUTY9~8: PWM3 duty data MSB 2 bits.

### 3.1.18 INTF2 (Interrupt Flag Register 2)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
INTF2	R	0x1F	ı	1	ı	EEWIF	ı	ı	ı	ı
R/W Property			-	-	-	R/W	-	-	-	-
Initial Value			X	X	Х	0	Х	Х	Х	Χ

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**EEWIF**: EEPROM write completion flag bit.

EEWIF=1, EEPROM write completion interrupt.

EEWIF must be clear by firmware.







### 3.2 T0MD Register

T0MD is a readable/writeable register which is only accessed by instruction T0MD / T0MDR.

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
T0MD	-	-	LCKTM0	GP6	T0CS	T0CE	PS0WDT	PS	SOSEL[2	2:0]
	R/W Property					R/W				
Initial Value(note*)		0	0	1	1	1		111		

PS0SEL[2:0]: Prescaler0 dividing rate selection. The rate depends on Prescaler0 is assigned to Timer0 or WDT. When Prescaler0 is assigned to WDT, the dividing rate is dependent on which timeout mechanism is selected.

		Dividing Rate	
PS0SEL[2:0]	PS0WDT=0 (Timer0)	PS0WDT=1 (WDT Reset)	PS0WDT=1 (WDT Interrupt)
000	1:2	1:1	1:2
001	1:4	1:2	1:4
010	1:8	1:4	1:8
011	1:16	1:8	1:16
100	1:32	1:16	1:32
101	1:64	1:32	1:64
110	1:128	1:64	1:128
111	1:256	1:128	1:256

Table 3 Prescaler0 Dividing Rate

PS0WDT: Prescaler0 assignment.

PS0WDT=1, Prescaler0 is assigned to WDT.

PS0WDT=0, Prescaler0 is assigned to Timer0.

Note: Always set PS0WDT and PS0SEL[2:0] before enabling watchdog or timer interrupt, or reset or interrupt may be falsely triggered.

**T0CE:** Timer0 external clock edge selection.

T0CE=1, Timer0 will increase one while high-to-low transition occurs on pin EX CKI.

T0CE=0, Timer0 will increase one while low-to-high transition occurs on pin EX\_CKI.

Note: T0CE is also applied to Low Oscillator Frequency as timer0 clock source condition.

T0CS: Timer0 clock source selection.

T0CS=1, External clock on pin EX CKI or Low Oscillator Frequency (I LRC) is selected.

T0CS=0, Instruction clock F<sub>INST</sub> is selected.

**LCKTM0:** When T0CS=1, timer 0 clock source can be optionally selected to be low-frequency oscillator.

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T0CS=0, Instruction clock F<sub>INST</sub> is selected as timer0 clock source.

T0CS=1, LCKTM0=0, external clock on pin EX CKI is selected as timer0 clock source.







T0CS=1, LCKTM0=1, Low Oscillator Frequency (I LRC) output replaces pin EX CKI as timer0 clock source.

GP6: General read/write register bit.

Note: For more detail descriptions of timer0 clock source select, please see timer0 section.

#### 3.3 F-page Special Function Register

#### 3.3.1 IOSTB (PortB I/O Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
IOSTB	F	0x6	-	-	IOPB5	IOPB4	IOPB3	IOPB2	IOPB1	IOPB0
R	R/W Property		-	-	R/W	R/W	R/W	R/W	R/W	R/W
	Initial Value			Х	1	1	1	1	1	1

**IOPBx:** PBx I/O mode selection,  $0 \le x \le 5$ .

IOPBx=1, PBx is input mode.

IOPBx=0, PBx is output mode.

GP7, GP6: General purpose register bit.

### 3.3.2 PS0CV (Prescaler0 Counter Value Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PS0CV	F	0xA				PS0C	V[7:0]			
R/W Property						F	3			
Initial Value			1	1	1	1	1	1	1	1

While reading PS0CV, it will get current value of Prescaler0 counter.

#### 3.3.3 **BODCON (PortB Open-Drain Control Register)**

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BODCON	F	0xC	GP7	GP6	ODPB5	ODPB4	ODPB3	ODPB2	ODPB1	ODPB0
R/W	Propert	у	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Initia	al Value	!	0	0	0	0	0	0	0	0

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**ODPBx:** Enable/disable open-drain of PBx,  $0 \le x \le 5$ .

ODPBx=1, enable open-drain of PBx.

ODPBx=0, disable open-drain of PBx.

GP7~6: General purpose register bit.



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### 3.3.4 PCON1 (Power Control Register1)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PCON1	F	0xF	GIE	LVDOUT	LVDS3	LVDS2	LVDS1	LVDS0	GP1	T0EN
R/V	V Propei	ty	R/W(1*)	R	R/W	R/W	R/W	R/W	R/W	R/W
lni	tial Valu	е	0	Х	0	1	1	1	0	1

T0EN: Enable/disable Timer0.

T0EN=1, enable Timer0.

T0EN=0, disable Timer0.

**GIE:** Global interrupt enable bit.

GIE=1, enable all unmasked interrupts.

GIE=0, disable all interrupts.

**GP1:** General purpose register bit.

(1\*): set by instruction ENI, clear by instruction DISI, read by instruction IOSTR.

LVDOUT: Low voltage detector output, read-only.

LVDS3~0 : Select one of the 16 LVD voltage.

LVDS[3:0]	Voltage
0000	1.8V
0001	2.0V
0010	2.2V
0011	2.4V
0100	2.7V
0101	2.8V
0110	2.9V
0111	3.0V
1000	3.3V
1001	3.6V
1010	3.7V
1011	3.8V
1100	3.9V
1101	4.0V
1110	4.1V
1111	4.15V

Table4 LVD voltage select



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### 3.4 S-page Special Function Register

#### 3.4.1 TMR1 (Timer1 Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TMR1	S	0x0	TMR1[7:0]							
R/W Property R/W										
	Initial Value		XXXXXXXX							

When reading register TMR1, it will obtain current value of 10-bit down-count Timer1 at TMR1[9:0]. When writing register TMR1, it will write data from TMRH[5:4] and Timer1 reload register to TMR1[9:0] current content.

#### 3.4.2 T1CR1 (Timer1 Control Register1)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
T1CR1	S	0x1	PWM10EN PWM10AL		-	-	-	T10S	T1RL	T1EN
R/W Property		W	W	7- (	-	-	R/W	R/W	R/W	
lı	Initial Value			0	Х	X	Х	0	0	0

This register is used to configure Timer1 functionality.

T1EN: Enable/disable Timer1.

T1EN=1, enable Timer1.

T1EN=0, disable Timer1.

T1RL: Configure Timer1 down-count mechanism while Non-Stop mode is selected (T1OS=0).

T1RL=1, initial value is reloaded from reload register TMR1[9:0].

T1RL=0, continuous down-count from 0x3FF when underflow is occurred.

**T10S:** Configure Timer1 operating mode while underflow is reached.

T1OS=1, One-Shot mode. Timer1 will count once from the initial value to 0x00.

T1OS=0, Non-Stop mode. Timer1 will keep down-count after underflow.

T10S	T1RL	Timer1 Down-Count Functionality
	0	Timer1 will count from reload value down to 0x00.
0	0	When underflow is reached, 0x3FF is reloaded and continues down-count.
0	4	Timer1 will count from reload value down to 0x00.
0	1	When underflow is reached, reload value is reloaded and continues to down-count.
1	.,	Timer1 will count from initial value down to 0x00.
'	Х	When underflow is reached, Timer1 will stop down-count.

Table 5 Timer1 Functionality

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**PWM1OAL:** Define PWM1 output active state.

PWM1OAL=1, PWM1 output is active low.

PWM1OAL=0, PWM1 output is active high.



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PWM10EN: Enable/disable PWM1 output.

PWM10EN=1, PWM1 output will be present on PB2.

PWM10EN=0, PB2 is GPIO.

### 3.4.3 T1CR2 (Timer1 Control Register2)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
T1CR2	S	0x2	-	-	T1CS	T1CE	/PS1EN	PS1SEL[2:0]		
	R/W Property			-	R/W	R/W	R/W	R/W	R/W	R/W
Initial Value			Х	Х	1	1	1	1	1	1

This register is used to configure Timer1 functionality.

**PS1SEL[2:0]:** Prescaler1 dividing rate selection.

PS1SEL[2:0]	Dividing Rate
000	1:2
001	1:4
010	1:8
011	1:16
100	1:32
101	1:64
110	1:128
111	1:256

Table 6 Prescaler1 Dividing Rate

Note: Always set PS1SEL[2:0] at /PS1EN=1, or interrupt may be falsely triggered.

/PS1EN: Disable/enable Prescaler1.

/PS1EN=1, disable Prescaler1.

/PS1EN=0, enable Prescaler1.

T1CE: Timer1 external clock edge selection.

T1CE=1, Timer1 will decrease one while high-to-low transition occurs on pin EX\_CKI.

T1CE=0, Timer1 will decrease one while low-to-high transition occurs on pin EX\_CKI.

T1CS: Timer1 clock source selection.

T1CS=1, External clock on pin EX\_CKI is selected.

T1CS=0, Instruction clock is selected.

### 3.4.4 PWM1DUTY (PWM1 Duty Register)

Name S	SFR Type Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
--------	----------------	------	------	------	------	------	------	------	------







			NY8AE51D
PWM1DUTY	S	0x3	PWM1DUTY[7:0]
RΛ	N Property		W
In	itial Value		XXXXXXXX

The reload value of 10-bit Timer1 stored on registers TMRH[5:4] and TMR1[7:0] is used to define the PWM1 frame rate, and registers TMRH[1:0] and PWM1DUTY[7:0] is used to define the duty cycle of PWM1.

### 3.4.5 PS1CV (Prescaler1 Counter Value Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PS1CV	8	0x4	PS1CV[7:0]							
R/W Property R										
	Initial Value	1	1	1	1	1	1	1	1	

While reading PS1CV, it will get current value of Prescaler1 counter.

### 3.4.6 BZ1CR (Buzzer1 Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
BZ1CR	S	0x5	BZ1EN	- 1	-	-		BZ1FS	EL[3:0]	
R/W Property			W	-	-	-		1	N	
	Initial Value	0	X	Х	X	1	1	1	1	

### BZ1FSEL[3:0]: Frequency selection of BZ1 output.

D745051 (2.01	BZ1 Frequenc	cy Selection
BZ1FSEL[3:0]	Clock Source	Dividing Rate
0000		1:2
0001		1:4
0010		1:8
0011	Dropoolor1 output	1:16
0100	Prescaler1 output	1:32
0101		1:64
0110		1:128
0111		1:256
1000		Timer1 bit 0
1001		Timer1 bit 1
1010		Timer1 bit 2
1011	Timer1 output	Timer1 bit 3
1100		Timer1 bit 4
1101		Timer1 bit 5
1110		Timer1 bit 6

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BZ1FSEL[3:0]	BZ1 Frequency Selection						
	Clock Source	Dividing Rate					
1111		Timer1 bit 7					

Table 7 Buzzer1 Output (PB2) Frequency Selection

BZ1EN: Enable/Disable BZ1 output.

BZ1EN=1, enable Buzzer1.

BZ1EN=0, disable Buzzer1.

### 3.4.7 IRCR (IR Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
IRCR	S	0x6	-	-	-	-	-	IRCSEL	IRF57K	IREN
	R/W Property	-	-	-	-	-	W	W	W	
	Initial Value	Х	Х	X	X	X	0	0	0	

IREN: Enable/Disable IR carrier output.

IREN=1, enable IR carrier output.

IREN=0, disable IR carrier output.

IRF57K: Selection of IR carrier frequency.

IRF57K=1, IR carrier frequency is 57KHz.

IRF57K=0, IR carrier frequency is 38KHz.

IRCSEL: Polarity selection of IR carrier.

IRCSEL=0, IR carrier will be generated when I/O pin data is 1.

IRCSEL=1, IR carrier will be generated when I/O pin data is 0.

#### Note:

### 1. Only high oscillation ( $F_{HOSC}$ ) (See section 3.14) can be used as IR clock source.

OSC. Type	57KHz	38KHz	Conditions
High IRC(4MHz)	64	96	HIRC mode (the input to IR module is set to 4MHz no matter what system clock is)

Table 8 Division ratio for different oscillation type

#### TBHP (Table Access High Byte Address Pointer Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TBHP	S	0x7	ı	ı	-	-	ı	-	TBHP1	TBHP0
I	R/W Property	1	-	-	-	-	-	-	R/W	R/W
	Initial Value		Х	Х	Х	Х	Х	Х	Х	Х

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When instruction CALLA, GOTOA or TABLEA is executed, the target address is constituted by TBHP[1:0] and ACC. ACC is the Low Byte of PC[9:0] and TBHP[1:0] is the high byte of PC[9:0]. GP2 is general register for NY8AE51D.

#### 3.4.9 TBHD (Table Access High Byte Data Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TBHD	S	0x8	-	-	TBHD5	TBHD4	TBHD3	TBHD2	TBHD1	TBHD0
F	R/W Property		-	-	R	R	R	R	R	R
	Initial Value		Х	Х	Х	Х	Х	Х	Х	Х

When instruction TABLEA is executed, high byte of content of addressed ROM is loaded into TBHD[5:0] register. The Low Byte of content of addressed ROM is loaded to ACC.

### 3.4.10 P2CR1 (PWM2 Control Register1)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
P2CR1	S	0xA	PWM2OEN	PWM2OAL	-	-	-	-	-	-
	R/W Property		W	W	-	-	-	-	-	-
	Initial Value		0	0	X	X	Х	Х	Х	Х

This register is used to configure PWM2 functionality.

PWM2OAL: Define PWM2 output active state.

PWM2OAL=1, PWM2 output is active low.

PWM2OAL=0, PWM2 output is active high.

PWM2OEN: Enable/disable PWM2 output.

PWM2OEN=1, PWM2 output will be present on PB0.

### 3.4.11 PWM2DUTY (PWM2 Duty Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PWM2DUTY	S	0xC	PWM2DUTY[7:0]							
R/V	V Property		W							
Ini	itial Value		XXXXXXXX							

The reload value of 10-bit Timer1 stored on registers TMRH[5:4] and TMR1[7:0] is used to define the PWM2 frame rate, and registers TMRH[3:2] and PWM2DUTY[7:0] is used to define the duty cycle of PWM2.

#### 3.4.12 OSCCR (Oscillation Control Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
OSCCR	S	0xF	-	-	-	-	ОРМІ	D[1:0]	STPHOSC	SELHOSC
F	R/W Property		ı	-	1	-	R/	W	R/W	R/W

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							<i>(8AE51D</i>
Initial Value	Х	Х	Х	Х	00	0	1

**SELHOSC:** Selection of system oscillation (F<sub>OSC</sub>).

SELHOSC=1, F<sub>OSC</sub> is high-frequency oscillation (F<sub>HOSC</sub>). SELHOSC=0, F<sub>OSC</sub> is low-frequency oscillation (F<sub>LOSC</sub>).

**STPHOSC:** Disable/enable high-frequency oscillation (F<sub>HOSC</sub>).

STPHOSC=1, F<sub>HOSC</sub> will stop oscillation and be disabled.

STPHOSC=0, F<sub>HOSC</sub> keep oscillation.

**OPMD[1:0]:** Selection of operating mode.

OPMD[1:0]	Operating Mode
00	Normal mode
01	Halt mode
10	Standby mode
11	reserved

Table 9 Selection of Operating Mode by OPMD[1:0]

Note: STPHOSC cannot be changed with SELHOSC or OPMD at the same time. STPHOSC cannot be changed with OPMD at the same time during SELHOSC=1.

### 3.4.13 P3CR1 (PWM3 Control Register1)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
P3CR1	S	0x11	PWM30EN	PWM3OAL	-	-	-	-	-	-
R	/W Property		W	W	-	-	-	-	-	-
	Initial Value		0	0	Х	Х	Х	Х	Х	Х

This register is used to configure PWM3 functionality.

PWM3OAL: Define PWM3 output active state.

PWM3OAL=1, PWM3 output is active low.

PWM3OAL=0, PWM3 output is active high.

PWM30EN: Enable/disable PWM3 output.

PWM3OEN=1, PWM3 output will be present on PB1.

### 3.4.14 PWM3DUTY (PWM3 Duty Register)

Name	SFR Type	Addr.	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
PWM3DUTY	S	0x13	PWM3DUTY[7:0]							
R/V	V Property		W							
In	itial Value		XXXXXXXX							

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The reload value of 10-bit Timer1 stored on registers TMRH[5:4] and TMR1[7:0] is used to define the PWM3 frame rate, and registers PWM3RH[1:0] and PWM3DUTY[7:0] is used to define the duty cycle of PWM3.

#### 3.5 I/O Port

NY8AE51D provide 6 I/O pins which are PB[5:0]. User can read/write these I/O pins through register PORTB. Each I/O pin has a corresponding register bit to define it is input pin or output pin. Register IOSTB[5:0] define the input/output direction of PB[5:0].

When an I/O pin is configured as input pin, it may have Pull-High resistor or Pull-Low resistor which is enabled or disabled through registers. Register BPHCON[5:0] are used to enable or disable Pull-High resistor of PB[5:0]. Register BPLCON[7:4] are used to enable or disable Pull-Low resistor of PB[3:0].

When an I/O pin is configured as output pin, there is a corresponding and individual register to select as Open-Drain output pin. Register BODCON[5:0] determine PB[5:0] is Open-Drain or not.

The summary of Pad I/O feature is listed in the table below.

	Feature	PB[3:0]	PB[5:4]
lanut	Pull-High Resistor	V	V
Input	Pull-Low Resistor	V	X
Output	Open-Drain	V	V

Table 10 Summary of Pad I/O Feature

The level change on each I/O pin of PB may generate interrupt request. Register BWUCON[5:0] will select which I/O pin of PB may generate this interrupt. As long as any pin of PB is selected by corresponding bit of BWUCON, the register bit PBIF (INTF[1]) will set to 1 if there is a level change occurred on any selected pin. An interrupt request will occur and interrupt service routine will be executed if register bit PBIE (INTE[1]) and GIE (PCON1[7]) are both set to 1.

There is one external interrupt provided by NY8AE51D. When register bit EIS (INTEDG[4]) is set to 1, PB0 is used as input pin for external interrupt.

Note: When PB0 is both set as level change operation and external interrupt, the external interrupt will have higher priority, and the PB0 level change operation will be disabled. But PB5~PB1 level change function are not affected.

NY8AE51D can provide IR carrier generation. IR carrier generation is enabled by register bit IREN (IRCR[0]) and carrier will be present on a PB1 pin.

PB3 can be used as external reset input determined by a configuration word. When an active-low signal is applied to PB3, it will cause NY8AE51D to enter reset process.

When NY8AE51D is in Normal mode or Standby mode, instruction clock is observable on PB4 if a configuration word is enabled.

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Moreover, PB2 can be timer 0 external clock source EX\_CKI if T0MD T0CS=1 and LCK\_TM0=0. PB2 can be timer 1 external clock source if T1CS=1.

Moreover, PB2 can be PWM output if T1CR1[7] PWM1OEN=1 and corresponding PB.2 configuration word. PB2 can also be Buzzer output if BZ1CR[7] BZ1EN=1 and corresponding PB.2 configuration word.



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#### 3.5.1 **Block Diagram of IO Pins**

IO\_SEL: set pad attribute as input or output.

WRITE EN: write data to pad.

READ\_EN: read pad.

OD\_EN: enable open-Drain.

PULLUP ENB: enable Pull-High.

PULLDOWN\_EN: enable Pull-Low.

RD\_TYPE: select read pin or read latch.

SFEN: Special-function enable (PWM2)

SFDT: Special-function data.

EIS: external interrupt function enable.

INTEDGE: external interrupt edge select.

EX\_INT: external interrupt signal.

WUB: port B wake-up enable.

SET\_PBIF: port B wake-up flag.

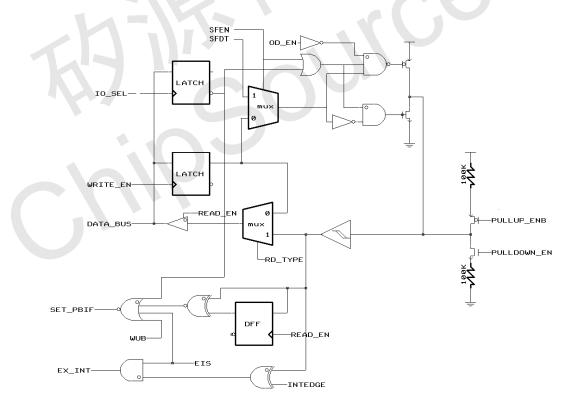


Figure 5 Block Diagram of PB0

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IO\_SEL: set pad attribute as input or output.

WRITE\_EN: write data to pad.

READ\_EN: read pad.

OD\_EN: enable open-Drain.

PULLUP\_ENB: enable Pull-High.

PULLDOWN\_EN: enable Pull-Low.

RD\_TYPE: select read pin or read latch.

SFEN: Special-function enable (IR)

SFDT: Special-function data.

WUB: port B wake-up enable.

SET\_PBIF: port B wake-up flag.

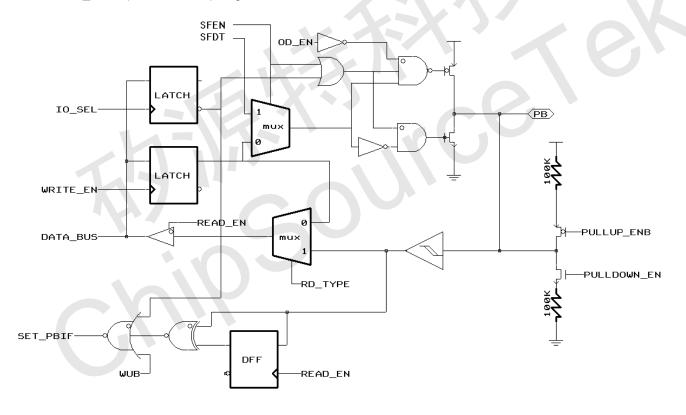


Figure 6 Block Diagram of PB1



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IO\_SEL: set pad attribute as input or output.

WRITE\_EN: write data to pad.

READ\_EN: read pad.

OD\_EN: enable open-Drain.

PULLUP\_ENB: enable Pull-High.

PULLDOWN\_EN: enable Pull-Low.

RD\_TYPE: select read pin or read latch.

SFEN: Special-function enable (PMW1/BUZZER1).

SFDT: Special-function data data.

WUB: port B wake-up enable.

SET\_PBIF: port B wake-up flag.

EX CKI: external clock input.

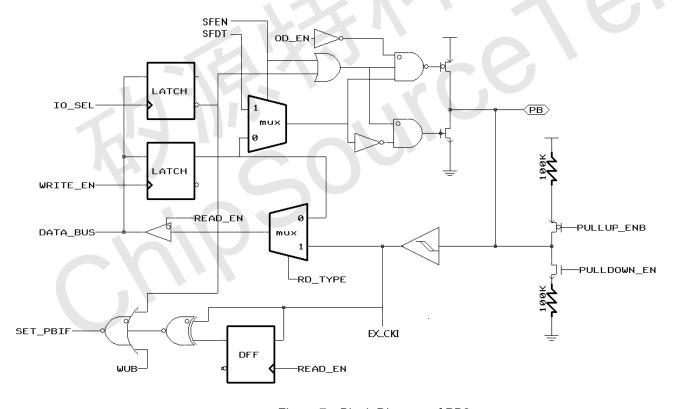


Figure 7 Block Diagram of PB2

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IO\_SEL: set pad attribute as input or output.

WRITE\_EN: write data to pad.

READ\_EN: read pad.

RSTPAD\_EN: reset pad enable.

RSTB\_IN: reset pad input.

PULLUP\_ENB: enable Pull-High.

PULLDOWN\_EN: enable Pull-Low.

RD\_TYPE: select read pin or read latch.

WUB: port B wake-up enable.

SET\_PBIF: port B wake-up flag.

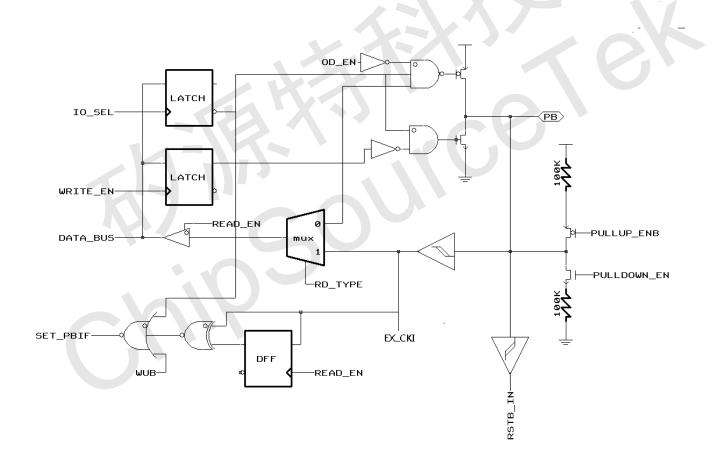


Figure 8 Block Diagram of PB3



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IO\_SEL: set pad attribute as input or output.

WRITE\_EN: write data to pad.

READ\_EN: read pad.

OD\_EN: enable open-Drain.

PULLUP\_ENB: enable Pull-High.

RD\_TYPE: select read pin or read latch.

WUB: port B wake-up enable.

SET\_PBIF: port B wake-up flag.

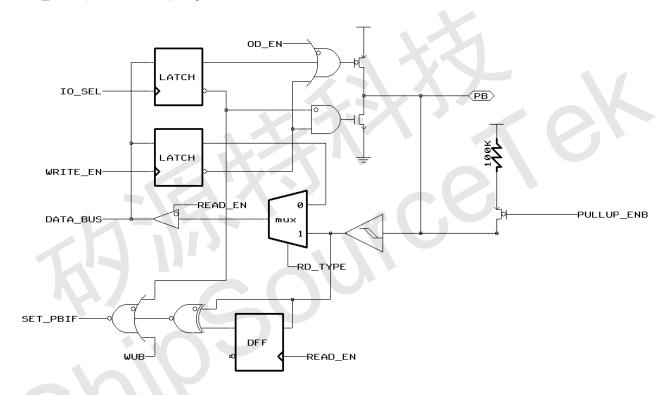


Figure 9 Block Diagram of PB4/PB5





#### Timer0 3.6

Timer0 is an 8-bit up-count timer and its operation is enabled by register bit T0EN (PCON1[0]). Writing to Timer0 will set its initial value. Reading from Timer0 will show its current count value.

The clock source to Timer0 can be from instruction clock, external pin EX\_CKI or low speed clock Low Oscillator Frequency according to register bit T0CS and LCK\_TM0 (T0MD[5] and T0MD[7]). When T0CS is 0, instruction clock is selected as Timer0 clock source. When T0CS is 1 and LCK TM0 is 0, EX CKI is selected as Timer0 clock source. When T0CS is 1 and LCK TM0 is 1 (and Timer0 source must set to 1), Low Oscillator Frequency (I LRC) output is selected. Summarized table is shown below. (Also check Table 10)

Timer0 clock source	TOCS	LCKTM0	Timer0 source
Instruction clock	0	Х	X
EX CVI	4	0	X
EX_CKI	'	Х	0
I_LRC	1	1	1

Table 11 Summary of Timer0 clock source control

Moreover the active edge of EX CKI or Low Oscillator Frequency to increase Timer0 can be selected by register bit T0CE (T0MD[4]). When T0CE is 1, high-to-low transition on EX CKI or Low Oscillator Frequency will increase Timer0. When T0CE is 0, low-to-high transition on EX CKI or Low Oscillator Frequency will increase Timer0.

Before Timer0 clock source is supplied to Timer0, it can be divided by Prescaler0 if register bit PS0WDT (T0MD[3]) is clear to 0. When writing 0 to PS0WDT by instruction, Prescaler0 is assigned to Timer0 and Prescaler0 will be clear after this instruction is executed. The dividing rate of Prescaler0 is determined by register bits PS0SEL[2:0] which is from 1:2 to 1:256.

Before entering Timer0, the Timer0 clock source synchronize with instruction clock in default. If EX CKI or Low Oscillator Frequency is used as Timer0 clock source, care must be taken that their frequency can not exceed instruction clock frequency, or missing count may happen. When Low Oscillator Frequency is both used as Timer0 clock source and instruction clock, NY8AE51D must assign prescaler0 to Timer0 and the prescaler0 dividing ratio must be no less than 4. There's a configuration word (EX CKI to Inst. Clock) which can relieve this constraint. When this option is set to Async, the Timer0 clock source does not synchronize with the instruction clock, so the input frequency of EX CKI can be higher than the instruction clock. The maximum frequency the EX CKI can input is depended on process variation.

When Timer0 is overflow, the register bit T0IF (INTF[0]) will be set to 1 to indicate Timer0 overflow event is occurred. If register bit T0IE (INTE[0]) and GIE are both set to 1, interrupt request will occur and interrupt service routine will be executed. TOIF will not be clear until firmware writes 0 to TOIF.

The block diagram of Timer0 and WDT is shown in the figure below.





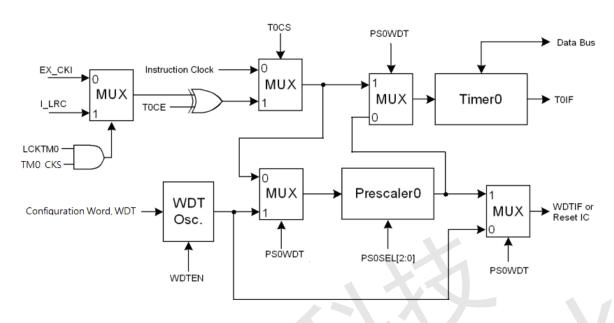


Figure 10 Block Diagram of Timer0 and WDT

#### Timer1/PWM1/Buzzer1 3.7

Timer1 is an 10-bit down-count timer with Prescaler1 whose dividing rate is programmable. The output of Timer1 can be used to generate PWM1 output and Buzzer1 output. Timer1 builds in auto-reload function and Timer1 reload register stores reload data with double buffers. When user write Timer1 reload register, write Timer1 MSB 2 bits(TMRH[5:4]) first and write TMR1 second, Timer1 reload register will be updated to Timer1 counter after Timer1 overflow occurs when T1EN=1. If T1EN=0, Timer1 reload register will be updated to Timer1 counter after write TMR1 immediately. A read to the Timer1 will show the content of the Timer1 current count value. The block diagram of Timer1 is shown in the figure below.

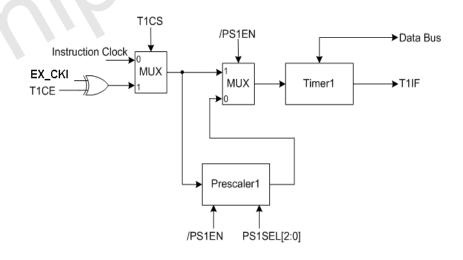


Figure 11 Block Diagram of Timer1



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The operation of Timer1 can be enabled or disabled by register bit T1EN (T1CR1[0]). After Timer1 is enabled, its clock source can be instruction clock or pin EX CKI which is determined by register bit T1CS (T1CR2[5]). When T1CS is 1, EX CKI is selected as clock source. When T1CS is 0, instruction clock is selected as clock source. When EX CKI is selected, the active edge to decrease Timer1 is determined by register bit T1CE (T1CR2[4]). When T1CE is 1, high-to-low transition on EX CKI will decrease Timer1. When T1CE is 0, low-to-high transition on EX CKI will decrease Timer1. The selected clock source can be divided further by Prescaler1 before it is applied to Timer1. Prescaler1 is enabled by writing 0 to register bit /PS1EN (T1CR2[3]) and the dividing rate is from 1:2 to 1:256 determined by register bits PS1SEL[2:0] (T1CR2[2:0]). Current value of Prescaler1 can be obtained by reading register PS1CV.

Timer1 provide two kinds of operating mode: one is One-Shot mode and the other is Non-Stop mode. When register bit T1OS (T1CR1[2]) is 1, One-Shot mode is selected. Timer1 will count down once from initial value stored on register TMR1 to 0x00, i.e. underflow is occurred. When register bit T1OS (T1CR1[2]) is 0, Non-Stop mode is selected. When underflow is occurred, there are two selections to start next down-count which is determined by register bit T1RL (T1CR1[1]). When T1RL is 1, the initial value stored on register TMR1 will be restored and start next down-count from this initial value. When T1RL is 0, Timer1 will start next down-count from 0x3FF.

When Timer1 is underflow, the register bit T1IF (INTF[3]) will be set to 1 to indicate Timer1 underflow event is occurred. If register bit T1IE (INTE[3]) and GIE are both set to 1, interrupt request will occur and interrupt service routine will be executed. T1IF will not be clear until firmware writes 0 to T1IF.

The timing chart of Timer1 is shown in the following figure.

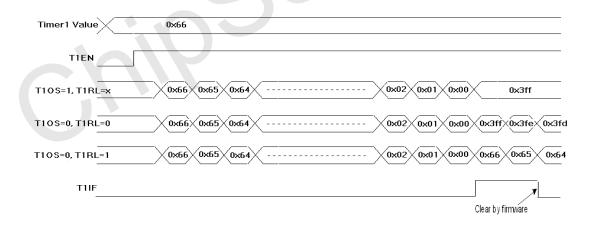


Figure 12 Timer1 Timing Chart

The PWM1 output can be available on I/O pin PB2 when register bit PWM10EN (T1CR1[7]) is set to 1. Moreover, PB2 will become output pin automatically. The active state of PWM1 output is determined by register bit PWM1OAL (T1CR1[6]). When PWM1OAL is 1, PWM1 output is active low. When PWM1OAL is 0, PWM1

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output is active high. Moreover, the duty cycle and frame rate of PWM1 are both programmable. The duty cycle is determined by registers TMRH[1:0] and PWM1DUTY[7:0]. When PWM1DUTY is 0, PWM1 output will be never active. When PWM1DUTY is 0x3FF, PWM1 output will be active for 1023 Timer1 input clocks. The frame rate is determined by TMRH[5:4] + TMR1[7:0] initial value. Therefore, PWM1DUTY value must be less than or equal to TMRH[5:4] + TMR1[7:0]. When user write PWM1DUTY, write PWM1DUTY[9:8] MSB 2 bits(TMRH[1:0]) first and write PWM1DUTY[7:0] second, PWM1 duty register will be updated after Timer1 overflow occurs. The block diagram of PWM1 is illustrated in the following figure.

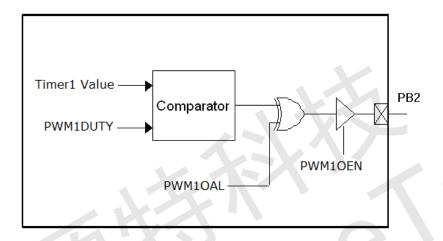


Figure 13 PWM1 Block Diagram

The Buzzer1 output (BZ1) can be available on I/O pin PB2, when register bit BZ1EN (BZ1CR1[7]) is set to 1 and corresponding configuration word PB.2 is BUZZER. When BZ1EN is set to 1, PB2 will become output pin automatically. The frequency of BZ1 can be derived from Timer1 output or Prescaler1 output and dividing rate is determined by register bits BZ1FSEL[3:0] (BZ1CR[3:0]). When BZ1FSEL[3] is 0, Prescaler1 output is selected to generate BZ1 output. When BZ1FSEL[3] is 1, Timer1 output is selected to generate BZ1 output. The dividing rate can be from 1:2 to 1:256 in order to generate all kinds of frequency. The block diagram of Buzzer1 is illustrated in the following figure.

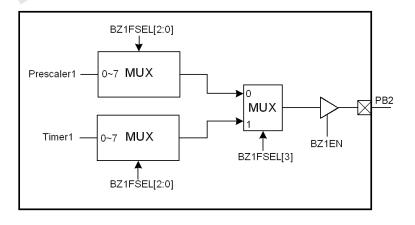


Figure 14 Buzzer1 Block Diagram

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#### PWM2 3.8

The PWM2 output can be available on I/O pin PB0 when register bit PWM2OEN (P2CR[7]) is set to 1. When PWM2OEN=1, PB0 will become output pin automatically. The active state of PWM2 output is determined by register bit PWM2OAL (P2CR[6]). When PWM2OAL is 1, PWM2 output is active low. When PWM2OAL is 0, PWM2 output is active high. Moreover, the duty cycle and frame rate of PWM2 are both programmable. The duty cycle is determined by register PWM2DUTY. When PWM2DUTY is 0, PWM2 output will be never active. When PWM2DUTY is 0x3FF, PWM2 output will be active for 1023 Timer1 input clocks. The frame rate is determined by TMRH[5:4],TMR1[7:0] initial value. Therefore, PWM2DUTY value must be less than or equal to TMR1[9:0]. When user write PWM2DUTY, write PWM2DUTY[9:8] MSB 2 bits(TMRH[3:2]) first and write PWM2DUTY[7:0] second, PWM2 duty register will be updated after Timer1 overflow occurs. The block diagram of PWM2 is illustrated in the following figure.

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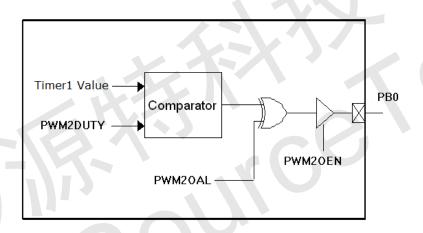


Figure 15 PWM2 Block Diagram

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### 3.9 PWM3

The PWM3 output can be available on I/O pin PB1 when register bit PWM3OEN (P3CR[7]) is set to 1. When PWM3OEN=1, PB1 will become output pin automatically. The active state of PWM3 output is determined by register bit PWM3OAL (P3CR[6]). When PWM3OAL is 1, PWM3 output is active low. When PWM3OAL is 0, PWM3 output is active high. Moreover, the duty cycle and frame rate of PWM3 are both programmable. The duty cycle is determined by register PWM3DUTY. When PWM3DUTY is 0, PWM3 output will be never active. When PWM3DUTY is 0x3FF, PWM3 output will be active for 1023 Timer1 input clocks. The frame rate is determined by TMRH[5:4],TMR1[7:0] initial value. Therefore, PWM3DUTY value must be less than or equal to TMR1[9:0]. When user write PWM3DUTY, write PWM3DUTY[9:8] MSB 2 bits(PWM3RH[1:0]) first and write PWM3DUTY[7:0] second, PWM3 duty register will be updated after Timer1 overflow occurs. The block diagram of PWM3 is illustrated in the following figure.

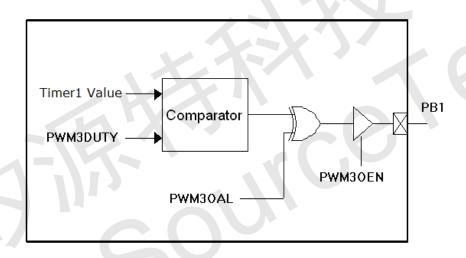


Figure 16 PWM3 Block Diagram

#### 3.10 IR Carrier

The IR carrier will be generated after register bit IREN (IRCR[0]) is set to 1. Moreover, PB1 will become output pin automatically. When IREN is clear to 0, PB1 will become general I/O pin as it was configured.

The IR carrier frequency is selectable by register bit IRF57K (IRCR[1]). When IRF57K is 1, IR carrier frequency is 57KHz. When IRF57K is 0, IR carrier frequency is 38KHz.

The active state (polarity) of IR carrier is selectable according to PB1 output data. When register bit IRCSEL (IRCR[2]) is 1, IR carrier will be present on pin PB1 when its output data is 0. When register bit IRCSEL (IRCR[2]) is 0, IR carrier will be present on pin PB1 when its output data is 1. The polarity of IR carrier is shown in the following figure.

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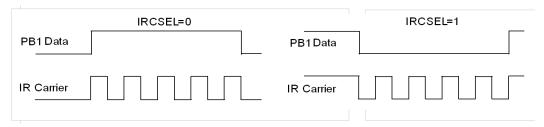


Figure 17 Polarity of IR Carrier vs. Output Data

### 3.11 Low Voltage Detector (LVD)

NY8AE51D low voltage detector (LVD) built-in precise band-gap reference for accurately detecting  $V_{DD}$  level. If LVDEN(register PCON[5])=1 and  $V_{DD}$  voltage value falls below LVD voltage which is selected by LVDS[3:0] as table shown below, the LVD output will become low. If the LVD interrupt is enabled, the LVD interrupt flag will be high and if GIE=1 it will force the program to execute interrupt service routine. Moreover, LVD real-state output can be polled by register PCON1[6]. The following is LVD block diagram:

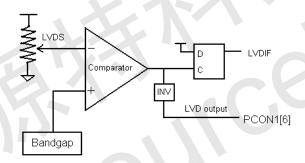


Figure 18 LVD block diagram

LVDS[3:0]	Voltage
0000	1.8V
0001	2.0V
0010	2.2V
0011	2.4V
0100	2.7V
0101	2.8V
0110	2.9V
0111	3.0V
1000	3.3V
1001	3.6V
1010	3.7V
1011	3.8V
1100	3.9V
1101	4.0V

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LVDS[3:0]	Voltage
1110	4.1V
1111	4.15V

### 3.12 Watch-Dog Timer (WDT)

There is an on-chip free-running oscillator in NY8AE51D which is used by WDT. As this oscillator is independent of other oscillation circuits, WDT may still keep working during Standby mode and Halt mode.

WDT can be enabled or disabled by a configuration word. When WDT is enabled by configuration word, its operation still can be controlled by register bit WDTEN (PCON[7]) during program execution. Moreover, the mechanism after WDT time-out can reset NY8AE51D or issue an interrupt request which is determined by another configuration word. At the same time, register bit /TO (STATUS[4]) will be clear to 0 after WDT time-out.

The baseline of WDT time-out period can be 3.5 ms, 15 ms, 60 ms or 250 ms which is determined by two configuration words. The time-out period can be lengthened if Prescaler0 is assigned to WDT. Prescaler0 will be assigned to WDT by writing 1 to register bit PS0WDT. The dividing rate of Prescaler0 for WDT is determined by register bits PS0SEL[2:0] and depends on WDT time-out mechanism. The dividing rate is from 1:1 to 1:128 if WDT time-out will reset NY8AE51D and dividing rate is from 1:2 to 1:256 if WDT time-out will interrupt NY8AE51D.

When Prescaler0 is assigned to WDT, the execution of instruction CLRWDT will clear WDT, Prescaler0 and set /TO flag to 1.

If user selects interrupt for WDT time-out mechanism, register bit WDTIF (INTF[6]) will set to 1 after WDT is expired. It may generate an interrupt request if register bit WDTIE (INTE[6]) and GIE both set to 1. WDTIF will not be clear until firmware writes 0 to WDTIF.

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### 3.13 Interrupt

NY8AE51D provide two kinds of interrupt: one is software interrupt and the other is hardware interrupt. Software interrupt is caused by execution of instruction INT. There are 7 hardware interrupts:

- Timer0 overflow interrupt.
- Timer1 underflow interrupt.
- WDT timeout interrupt.
- PB input change interrupt.
- External interrupt.
- LVD interrupt.
- End of EEPROM write interrupt.

GIE is global interrupt enable flag. It has to be 1 to enable hardware interrupt functions. GIE can be set by ENI instruction and clear to 0 by DISI instruction.

After instruction INT is executed, no matter GIE is set or clear, the next instruction will be fetched from address 0x001. At the same time, GIE will be clear to 0 by NY8AE51D automatically. This will prevent nested interrupt from happening. The last instruction of interrupt service routine of software interrupt has to be RETIE. Execution of this instruction will set GIE to 1 and return to original execution sequence.

While any of hardware interrupts is occurred, the corresponding bit of Interrupt Flag Register INTF will be set to 1. This bit will not be clear until firmware writes 0 to this bit. Therefore user can obtain information of which event causes hardware interrupt by polling register INTF. Note that only when the corresponding bit of Interrupt Enable register INTE is set to 1, will the corresponding interrupt flag be read. And if the corresponding bit of Interrupt Enable Register INTE is set to 1 and GIE is also 1, hardware interrupt will occur and next instruction will be fetched from 0x008. At the same time, the register bit GIE will be clear by NY8AE51D automatically. If user wants to implement nested interrupt, instruction ENI can be used as the first instruction of interrupt service routine which will set GIE to 1 again and allow other interrupt events to interrupt NY8AE51D again. Instruction RETIE has to be the last instruction of interrupt service routine which will set GIE to 1 and return to original execution sequence.

It should be noted that ENI instruction cannot be placed right before RETIE instruction because ENI instruction in interrupt service routine will trigger nested interrupt, but RETIE will clear internal interrupt processing after jump out of ISR, so it is possible for interrupt flag to be falsely cleared.

### 3.13.1 Timer0 Overflow Interrupt

Timer0 overflow (from 0x00 to 0xFF) will set register bit T0IF. This interrupt request will be serviced if T0IE and GIE are set to 1.



3.13.2 Timer1 Underflow Interrupt

Timer1 underflow (from 0x3FF to 0x00) will set register bit T1IF. This interrupt request will be serviced if T1IE and GIE are set to 1.

3.13.3 WDT Timeout Interrupt

When WDT is timeout and the configuration word selects WDT timeout will generate interrupt request, it will set register bit WDTIF. This interrupt request will be serviced if WDTIE and GIE are set to 1.

3.13.4 PB Input Change Interrupt

When PBx,  $0 \le x \le 5$ , is configured as input pin and corresponding register bit WUPBx is set to 1, a level change on these selected I/O pin(s) will set register bit PBIF. This interrupt request will be serviced if PBIE and GIE are set to 1. Note when PB0 is both set as level change interrupt and external interrupt, the external

interrupt flag EIS will disable PB0 level change operation.

3.13.5 External Interrupt

According to the configuration of EIS=1 and INTEDG, the selected active edge on I/O pin PB0 will set

register bit INTIF and this interrupt request will be served if INTIE and GIE are set to 1.

3.13.6 LVD Interrupt

When  $V_{DD}$  level falls below LVD voltage, LVD flag will go from high to low, and set the register bit LVDIF=1.

This interrupt request will be serviced if LVDIE and GIE are set to 1.

3.13.7 End of EEPROM write interrupt

When EEPROM write one byte completely, and set the register bit EEWIF=1. This interrupt request will be

serviced if EEWIE and GIE are set to 1.

3.14 Oscillation Configuration

Because NY8AE51D is a dual-clock IC, there are high oscillation (F<sub>HOSC</sub>) and low oscillation (F<sub>LOSC</sub>) which can

be selected as system oscillation (Fosc). The oscillators which could be used as FHOSC are internal high RC

oscillator (I\_HRC). The oscillators which could be used as F<sub>LOSC</sub> are internal low RC oscillator (I\_LRC).

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- (1) STPHOSC(OSCCR[1])=1 will stop Fhosc
- (2) FHOSC will be disabled automatically at Halt mode

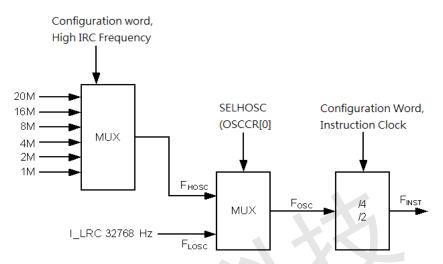


Figure 19 Oscillation Configuration of NY8AE51D

I\_HRC output frequency is determined by three configuration words and it can be 1M, 2M, 4M, 8M, 16M or 20MHz.

When I\_LRC is selected, its frequency is centered on 32768Hz.

Either  $F_{HOSC}$  or  $F_{LOSC}$  can be selected as system oscillation  $F_{OSC}$  according to the value of register bit SELHOSC (OSCCR[0]). When SELHOSC is 1,  $F_{HOSC}$  is selected as  $F_{OSC}$ . When SELHOSC is 0,  $F_{LOSC}$  is selected as  $F_{OSC}$ . Once  $F_{OSC}$  is determined, the instruction clock  $F_{INST}$  can be  $F_{OSC}/2$  or  $F_{OSC}/4$  according to value of a configuration word.

### 3.15 Operating Mode

NY8AE51D provides four kinds of operating mode to tailor all kinds of application and save power consumptions. These operating modes are Normal mode, Slow mode, Standby mode and Halt mode. Normal mode is designated for high-speed operating mode. Slow mode is designated for low-speed mode in order to save power consumption. At Standby mode, NY8AE51D will stop almost all operations except Timer0/Timer1/WDT/LVD in order to wake-up periodically. At Halt mode, NY8AE51D will sleep until external event or WDT trigger IC to wake-up.

The block diagram of four operating modes is described in the following figure.

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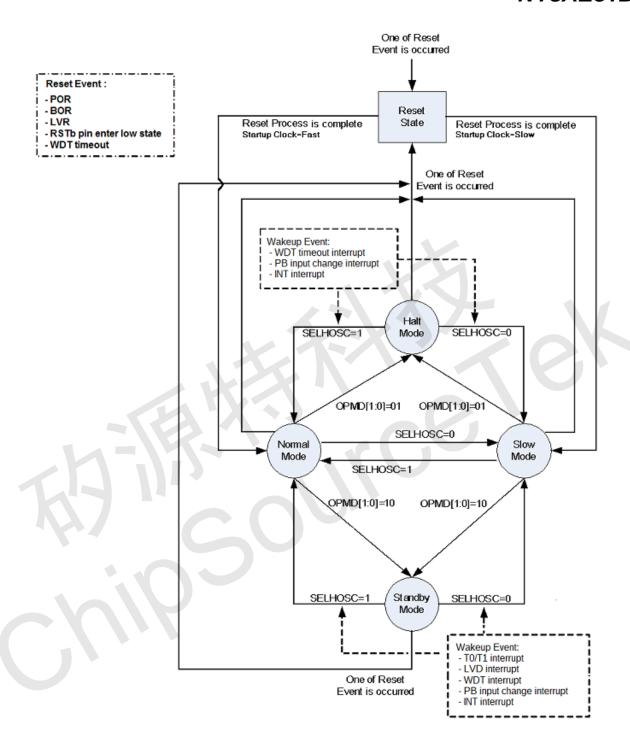


Figure 20 Four Operating Modes

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### 3.12.1 Normal Mode

After any Reset Event is occurred and Reset Process is complete, NY8AE51D will begin to execute program under Normal mode or Slow mode. Which mode is selected after Reset Process is determined by the Startup Clock configuration word. If Startup Clock= I HRC, NY8AE51D will enter Normal mode, if Startup Clock= I\_LRC, NY8AE51D will enter Slow mode. At Normal mode, F<sub>HOSC</sub> is selected as system oscillation in order to provide highest performance and its power consumption will be the largest among four operating modes. After power on or any reset trigger is released, NY8AE51D will enter Normal mode after reset process is complete.

- Instruction execution is based on F<sub>HOSC</sub> and all peripheral modules may be active according to corresponding module enable bit.
- The F<sub>LOSC</sub> is still active and running.
- IC can switch to Slow mode by writing 0 to register bit SELHOSC (OSCCR[0]).
- IC can switch to Standby mode or Halt mode by programming register bits OPMD[1:0] (OSCCR[3:2]).
- For real time clock applications, the NY8AE51D can run in normal mode, at the same time the low-frequency clock. Low Oscillator Frequency connects to timer0 clock. This is made possible by setting LCKTM0 to 1 and corresponding configuration word Timer0 source setting to 1.

#### 3.12.2 Slow Mode

NY8AE51D will enter Slow mode by writing 0 to register bit SELHOSC. At Slow mode, FLOSC is selected as system oscillation in order to save power consumption but still keep IC running. However, F<sub>HOSC</sub> will not be disabled automatically by NY8AE51D. Therefore user can write 0 to register bit STPHOSC (OSCCR[1]) in slow mode to reduce power consumption further. But it is noted that it is forbidden to enter slow mode and stop F<sub>HOSC</sub> at the same time, one must enter slow mode first, then disable F<sub>HOSC</sub>, or the program may hang on.

- Instruction execution is based on F<sub>LOSC</sub> and all peripheral modules may be active according to corresponding module enable bit.
- F<sub>HOSC</sub> can be disabled by writing 1 to register bit STPHOSC.
- IC can switch to Standby mode or Halt mode by programming register bits OPMD[1:0].
- IC can switch to Normal mode by writing 1 to SELHOSC.

### 3.12.3 Standby Mode

NY8AE51D will enter Standby mode by writing 10b to register bits OPMD[1:0]. At Standby mode, however, F<sub>HOSC</sub> will not be disabled automatically by NY8AE51D and user has to enter slow mode and write 1 to register bit STPHOSC in order to stop F<sub>HOSC</sub> oscillation. Most of NY8AE51D peripheral modules are disabled but Timer can be still active if register bit T0EN/T1EN is set to 1. Therefore NY8AE51D can wake-up after Timer0/Timer1 is expired. The expiration period is determined by the register TMR0/TMR1, F<sub>INST</sub> and other configurations for Timer0/Timer1.

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- Instruction execution is stop and some peripheral modules may be active according to corresponding module enable bit.
- F<sub>HOSC</sub> can be disabled by writing 1 to register bit STPHOSC.
- The F<sub>LOSC</sub> is still active and running.
- IC can wake-up from Standby mode if any of (a) Timer0 overflow /Timer1 underflow interrupt, (b) WDT timeout interrupt, (c) PB input change interrupt, (d) INT external interrupt is happened or (e) LVD Interrupt.
- After wake-up from Standby mode, IC will return to Normal mode if SELHOSC=1, IC will return to Slow mode if SELHOSC=0.
- It is not recommended to change oscillator mode (normal to slow / slow to normal) and enter standby mode at the same time.

#### 3.12.4 Halt Mode

NY8AE51D will enter Halt mode by executing instruction SLEEP or writing 01b to register bits OPMD[1:0]. After entering Halt mode, register bit /PD (STATUS[3]) will be clear to 0, register bit /TO (STATUS[4]) will be set to 1 and WDT will be clear but keep running.

At Halt mode, all of peripheral modules are disabled, instruction execution is stop and NY8AE51D can only wake-up by some specific events. Therefore, Halt mode is the most power saving mode provided by NY8AE51D.

- Instruction execution is stop and all peripheral modules are disabled.
- F<sub>HOSC</sub> and F<sub>LOSC</sub> are both disabled automatically.
- IC can wake-up from Halt mode if any of (a) WDT timeout interrupt, (b) PB input change interrupt or (c) INT or external interrupt is happened.
- After wake-up from Halt mode, IC will return to Normal mode if SELHOSC=1, IC will return to Slow mode if SELHOSC=0.

Note: you can change STPHOSC and enter Halt mode in the same instruction.

It is not recommended to change oscillator mode (normal to slow / slow to normal) and enter standby mode at the same time

### 3.12.5 Wake-up Stable Time

The wake-up stable time of Halt mode is 16\*Fosc, There is no need of wake-up stable time for Standby mode because either F<sub>HOSC</sub> or F<sub>LOSC</sub> is still running at Standby mode.

Before NY8AE51D enters Standby mode or Halt mode, user may execute instruction ENI. At this condition, NY8AE51D will branch to address 0x008 in order to execute interrupt service routine after wake-up. If instruction DISI is executed before entering Standby mode or Halt mode, the next instruction will be executed after wake-up.

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### 3.12.6 Summary of Operating Mode

The summary of four operating modes is described in the following table.

Mode	Normal	Slow	Standby	Halt
F <sub>HOSC</sub>	Enabled	STPHOSC	STPHOSC	Disabled
F <sub>LOSC</sub>	Enabled	Enabled	Enabled	Disabled
Instruction Execution	Executing	Executing	Stop	Stop
Timer0/1	T0EN / T1EN	T0EN / T1EN	T0EN / T1EN	Disabled
WDT	Option and WDTEN	Option and WDTEN	Option and WDTEN	Option and WDTEN
Other Modules	Module enable bit	Module enable bit	Module enable bit	All disabled
Wake-up Source	-		- Timer0 overflow - Timer1 underflow - WDT timeout - PB input change - INT - LVD	- WDT timeout - PB input change - INT

Table 12 Summary of Operating Modes

#### 3.16 Reset Process

NY8AE51D will enter Reset State and start Reset Process when one of following Reset Event is occurred:

- Power-On Reset (POR) is occurred when V<sub>DD</sub> rising is detected.
- Low-Voltage Reset (LVR) is occurred when operating V<sub>DD</sub> is below pre-defined voltage.
- Pin RSTb is low state.
- WDT timeout reset.

Moreover, value of all registers will be initialized to their initial value or unchanged if its initial value is unknown. The status bits /TO and /PD could be initialized according to which event causes reset. The /TO and /PD value and its associated event is summarized in the table below.

Event	/TO	/PD
POR, LVR	1	1
RSTb reset from non-Halt mode	unchanged	unchanged
RSTb reset from Halt mode	1	1
WDT reset from non-Halt mode	0	1
WDT reset from Halt mode	0	0
SLEEP executed	1	0
CLRWDT executed	1	1

Table 13 Summary of /TO & /PD Value and its Associated Event



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After Reset Event is released, NY8AE51D will start Reset Process. It will wait certain amount of period for oscillation stable no matter what kind of oscillator is adopted. This period is called power-up reset time and is determined by three-bit configuration words which can be 140u, 4.5ms, 18ms, 72ms or 288ms. After oscillator is stable, NY8AE51D will wait further 16 clock cycles of F<sub>OSC</sub> (oscillator start-up time, OST) and Reset Process is complete.

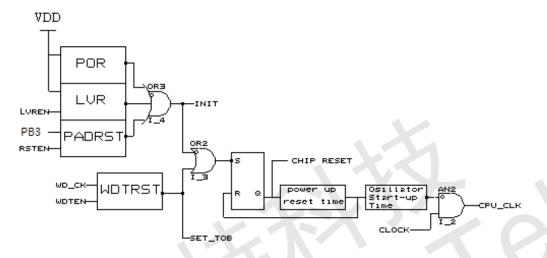


Figure 21 Block diagram of on-chip reset circuit

For slow V<sub>DD</sub> power-up, it is recommended to use RSTb reset, as the following figure.

- It is recommended the R value should be not greater than 40kΩ.
- The R1 value=100Ω to 1kΩ will prevent high current, ESD or Electrical overstress flowing into reset pin.
- The diode helps discharge quickly when power down.

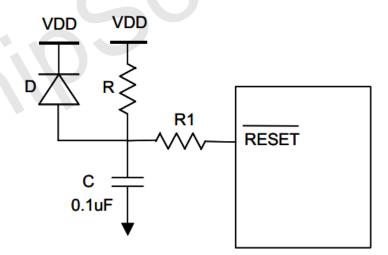


Figure 22 Block Diagram of Reset Application

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### 4. Instruction Set

NY8AE51D provides 53 powerful instructions for all kinds of applications.

lnc4	OP		Operation	Cyra	Elec	
Inst.	1	2	Operation	Cyc.	Flag	
Arithmeti	Arithmetic Instructions					
ANDAR	R	d	dest = ACC & R	1	Z	
IORAR	R	d	dest = ACC   R	1	Z	
XORAR	R	d	dest = ACC ⊕ R	1	Z	
ANDIA	i		ACC = ACC & i	1	Z	
IORIA	i		ACC = ACC   i	1	Z	
XORIA	i		ACC = ACC ⊕ i	1	Z	
RRR	R	d	Rotate right R	1	С	
RLR	R	d	Rotate left R	1	С	
BSR	R	bit	Set bit in R	1	-	
BCR	R	bit	Clear bit in R	1	-	
INCR	R	d	Increase R	1	Z	
DECR	R	d	Decrease R	1	Z	
COMR	R	d	dest = ~R	1	Z	
Condition	al II	nstru	uctions	7		
BTRSC	R	bit	Test bit in R, skip if clear	1 or 2	-	
BTRSS	R	bit	Test bit in R, skip if set	1 or 2	-	
INCRSZ	R	d	Increase R, skip if 0	1 or 2	-	
DECRSZ	R	d	Decrease R, skip if 0	1 or 2	-	
Data Tran	sfer	Ins	tructions			
MOVAR	R		Move ACC to R	1	-	
MOVR	R	d	Move R	1	Z	
MOVIA	i		Move immediate to ACC	1	-	
SWAPR	R	d	Swap halves R	1	-	
IOST	F		Load ACC to F-page SFR	1	-	
IOSTR	F		Move F-page SFR to ACC	1	-	
SFUN	S		Load ACC to S-page SFR 1		-	
SFUNR	S		Move S-page SFR to ACC	1	-	
T0MD			Load ACC to T0MD	1	-	

Inct	0	Р	Operation		Flag
Inst.	1	2			ı iay
Arithmetic	c In	strı	ıctions		
ADDAR	R	d	dest = R + ACC	1	Z, DC, C
SUBAR	R	d	dest = R + (~ACC)	1	Z, DC, C
ADCAR	R	d	dest = R + ACC + C	1	Z, DC, C
SBCAR	R	d	dest = R + (~ACC) + C	1	Z, DC, C
ADDIA	ï		ACC = i + ACC	1	Z, DC, C
SUBIA	i	,	ACC = i + (~ACC)	1	Z, DC, C
ADCIA	i	•	ACC = i + ACC + C	1	Z, DC, C
SBCIA	i		ACC = i + (~ACC) + C	1	Z, DC, C
DAA			Decimal adjust for ACC	7	С
CMPAR	R		Compare R with ACC	1	Z, C
CLRA			Clear ACC	1	Z
CLRR			Clear R	1	Z
Other Inst	truc	tio	15		
NOP			No operation	1	-
SLEEP			Go into Halt mode	1	/TO, /PD
CLRWDT			Clear Watch-Dog Timer	1	/TO, /PD
ENI			Enable interrupt	1	-
DISI			Disable interrupt	1	-
INT			Software Interrupt	3	-
RET			Return from subroutine	2	-
RETIE			Return from interrupt	2	
KETIE			and enable interrupt	2	-
DETIA			Return, place immediate	2	
RETIA i			in ACC	2	
CALLA			Call subroutine by ACC	2	-
GOTOA			unconditional branch by ACC 2		-
LCALL	a	dr	r Call subroutine 2		-
LGOTO	a	dr	unconditional branch	2	-



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Table 14 Instruction Set

Inst.	Operation	Сус.	Flag
Other Ins	tructions		
EEAR	Read EEA to ACC	1	
EEAW	Write EEA from ACC	1	
EEDR	Read EED to ACC	1	
EEDW	Write EED from ACC	1	
EERD	Read EEA & Write EED reg	1	
EEWR	Write EEA & From EED reg	1	
EEPL	Write serial code to unlock	1	

ACC: Accumulator.

adr: immediate address.

bit: bit address within an 8-bit register R.

C: Carry/Borrow bit

C=1, carry is occurred for addition instruction or borrow is NOT occurred for subtraction instruction.

C=0, carry is not occurred for addition instruction or borrow **IS** occurred for subtraction instruction.

d: Destination

If d is "0", the result is stored in the ACC.

If d is "1", the result is stored back in register R.

DC: Digital carry flag.

dest: Destination.

F: F-page SFR, F is 0x5 ~ 0xF.

i: 8-bit immediate data.

PC: Program Counter.

PCHBUF: High Byte Buffer of Program Counter.

/PD: Power down flag bit

/PD=1, after power-up or after instruction CLRWDT is executed.

/PD=0, after instruction SLEEP is executed.

Prescaler: Prescaler0 dividing rate.

R: R-page SFR, R is 0x00 ~0x3F.

S: S-page SFR, S is  $0x0 \sim 0x13$ .

T0MD: T0MD register.

TBHP: The high-Byte at target address in ROM.

TBHD: Store the high-Byte data at target address in ROM.

/TO: Time overflow flag bit



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NY8AE51D

/TO=1, after power-up or after instruction CLRWDT or SLEEP is executed.

/TO=0, WDT timeout is occurred.

WDT: Watchdog Timer Counter.

Z: Zero flag.

TEL: +86-0755-27595155 27595165 FAX: +86-0755-27594792 WEB:Http://www.ChipSourceTek.com E-mail: Sales@ChipSourceTek.com Tony.Wang@ChipSourceTek.com

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ADCAR	Add ACC and R with Carry	ADDAR	NY8AE51D Add ACC and R
Syntax:	ADCAR R, d	Syntax:	ADDAR R, d
Operand:	$0 \le R \le 63$ d = 0, 1.	Operand:	$0 \le R \le 63$ d = 0, 1.
Operation:	$R + ACC + C \rightarrow dest$	Operation:	ACC + R → dest
Status affected:	Z, DC, C	Status affected:	Z, DC, C
Description:	Add the contents of ACC and register R with Carry. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.	Description:	Add the contents of ACC and R. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.
Cycle	1	Cycle:	1
Example:	ADCAR R, d before executing instruction:    ACC=0x12, R=0x34, C=1, d=1. after executing instruction:    R=0x47, ACC=0x12, C=0.	Example:	ADDAR R, d before executing instruction: ACC=0x12, R=0x34,C=1, d=1. after executing instruction: R=0x46, ACC=0x12, C=0.

ADCIA	Add ACC and Immediate with Carry	ADDIA	Add ACC and Immediate
Syntax:	ADCIA i	Syntax:	ADDIA i
Operand:	0 ≤ i < 255	Operand:	0 ≤ i < 255
Operation:	$ACC + i + C \rightarrow ACC$	Operation:	ACC + i→ACC
Status affected:	Z, DC, C	Status affected:	Z, DC, C
Description:	Add the contents of ACC and the 8-bit immediate data i with Carry. The result is placed in ACC.	Description:	Add the contents of ACC with the 8-bit immediate data i. The result is placed in ACC.
Cycle:	1	Cycle:	1
Example:	ADCIA i before executing instruction: ACC=0x12, i=0x34, C=1. after executing instruction: ACC=0x47, C=0.	Example:	ADDIA i before executing instruction: ACC=0x12, i=0x34, C=1. after executing instruction: ACC=0x46, C=0.







ANDAR	AND ACC and R	BCR	NY8AE51D Clear Bit in R
Syntax:	ANDAR R, d	Syntax:	BCR R, bit
Operand:	$0 \le R \le 63.$ d = 0, 1.	Operand:	$0 \le R \le 63$ $0 \le bit \le 7$
Operation:	ACC & R → dest	Operation:	$0 \rightarrow R[bit]$
Status affected:	Z	Status affected:	
Description:	The content of ACC is AND'ed with R. If d is 0, the result is stored in ACC. If d is 1, the result is stored	Description: Cycle:	Clear the bit <sup>th</sup> position in R. 1
	back to R.	Example:	BCR R,B2
Cycle:	1		before executing instruction: R=0x5A, B2=0x3.
Example:	ANDAR R, d before executing instruction: ACC=0x5A, R=0xAF, d=1. after executing instruction: R=0x0A, ACC=0x5A, Z=0.		after executing instruction: R=0x52.

ANDIA	AND Immediate with ACC	BSR	Set Bit in R
Syntax:	ANDIA i	Syntax:	BSR R, bit
Operand:	0 ≤ i < 255	Operand:	$0 \le R \le 63$
Operation:	ACC & i → ACC		$0 \le \text{bit} \le 7$
Status affected:	Z	Operation:	$1 \rightarrow R[bit]$
Description:	The content of ACC register is	Status affected:	
•		Description:	Set the bit <sup>th</sup> position in R.
	AND'ed with the 8-bit immediate	Cycle:	1
	data i. The result is placed in ACC.	Example:	BSR R,B2
Cycle:	1		before executing instruction:
Example:	ANDIA i		R=0x5A, B2=0x2.
	before executing instruction: ACC=0x5A, i=0xAF.		after executing instruction: R=0x5E.
	after executing instruction: ACC=0x0A, Z=0.		

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BTRSC	Test Bit in R and Skip if Clear	CALLA	NY8AE51D Call Subroutine
Syntax:	BTRSC R, bit	Syntax:	CALLA
Operand:	$0 \le R \le 63$	Operand:	
Operation:	$0 \le bit \le 7$ Skip next instruction, if R[bit] = 0.	Operation:	PC + 1 $\rightarrow$ Top of Stack {TBHP, ACC} $\rightarrow$ PC
Status affected:		Status affected:	
Description:	If R[bit] = 0, the next instruction which is already fetched is discarded and a NOP is executed instead. Therefore it makes this instruction a two-cycle instruction.	Description:	The return address (PC + 1) is pushed onto top of Stack. The contents of TBHP[1:0] is loaded into PC[9:8] and ACC is loaded into PC[7:0].
Cycle:	1 or 2(skip)	Cycle:	2
Example:	BTRSC R, B2 Instruction1 Instruction2 before executing instruction: R=0x5A, B2=0x2. after executing instruction: because R[B2]=0, instruction1 will not be executed, the program will start execute instruction from instruction2.	Example:	CALLA before executing instruction: TBHP=0x02, ACC=0x34. PC=A0. Stack pointer=1. after executing instruction: PC=0x234, Stack[1]=A0+1, Stack pointer=2.

BTRSS	Test Bit in R and Skip if Set	CLRA	Clear ACC
Syntax:	BTRSS R, bit	Syntax:	CLRA
Operand:	0 ≤ R ≤ 63	Operand:	
	$0 \le \text{bit} \le 7$	Operation:	$00h \rightarrow ACC$
Operation:	Skip next instruction, if R[bit] = 1.		1→ Z
Status affected:		Status affected:	Z
Description:	If R[bit] = 1, the next instruction	Description:	ACC is clear and Z is set to 1.
·	which is already fetched is	Cycle:	1
	discarded and a NOP is executed instead. Therefore it makes this instruction a two-cycle instruction.	Example:	CLRA before executing instruction: ACC=0x55, Z=0.
Cycle:	1 or 2(skip)		after executing instruction:
Example:	BTRSS R, B2 Instruction2 Instruction3 before executing instruction: R=0x5A, B2=0x3. after executing instruction: because R[B2]=1, instruction2 will not be executed, the program will start execute instruction from		ACC=0x00, Z=1.

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instruction3.



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CLRR	Clear R	COMR	NY8AE51D Complement R
Syntax:	CLRR R	Syntax:	COMR R, d
Operand:	$0 \le R \le 63$	Operand:	$0 \le R \le 63$
Operation:	$00h \rightarrow R$ $1 \rightarrow Z$	Operation:	d = 0, 1. ~R → dest
Status affected:	Z	Status affected:	Z
Description:	The content of R is clear and Z is set to 1.	Description:	The content of R is complemented. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to
Cycle:	1		R.
Example:	CLRR R	Cycle:	1
	before executing instruction: R=0x55, Z=0. after executing instruction: R=0x00, Z=1.	Example:	COMR, d before executing instruction: R=0xA6, d=1, Z=0. after executing instruction: R=0x59, Z=0.

CLRWDI	Clear Watch-Dog Timer	CMPAR	Compare ACC and R
Syntax:	CLRWDT	Syntax:	CMPAR R
Operand:		Operand:	0 ≤ R ≤ 63
Operation:	$00h \rightarrow WDT,$	Operation:	R - ACC → (No restore)
	00h → WDT prescaler 1 → /TO	Status affected:	Z, C
	1 →/PD	Description:	Compare ACC and R by
Status affected:	/TO, /PD		subtracting ACC from R with 2's complement representation. The
Description:	Executing CLRWDT will reset WDT, Prescaler0 if it is assigned to		content of ACC and R is not changed.
	WDT. Moreover, status bits /TO and /PD will be set to 1.	Cycle:	1
Cycle:	1	Example:	CMPAR R
Example:	CLRWDT before executing instruction: /TO=0 after executing instruction:		before executing instruction: R=0x34, ACC=12, Z=0, C=0. after executing instruction: R=0x34, ACC=12, Z=0, C=1.
	/TO=1		

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CL DWDT



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DAA	Convert ACC Data Format from	DECRSZ	NY8AE51D Decrease R, Skip if 0
Syntax:	DAA	Syntax:	DECRSZ R, d
Operand:		Operand:	$0 \le R \le 63$ d = 0, 1.
Operation:	$ACC(hex) \rightarrow ACC(dec)$	Operation:	R - 1 → dest,
Status affected:	С	Орогацоп.	Skip if result = 0
Description:	Convert ACC data format from hexadecimal to decimal after	Status affected:	-
	addition operation and restore result to ACC. DAA instruction must be placed immediately after addition operation if decimal format is required. Please note that interrupt should be disabled before addition instruction and enabled after DAA instruction to avoid unexpected result.	Description:	Decrease R first. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.  If result is 0, the next instruction which is already fetched is discarded and a NOP is executed instead. Therefore it makes this instruction a two-cycle instruction.
Cycle:	1	Cycle:	1 or 2(skip)
Example:	DISI ADDAR R,d DAA ENI before executing instruction: ACC=0x28, R=0x25, d=0. after executing instruction: ACC=0x53, C=0.	Example:	DECRSZ R, d instruction2 instruction3 before executing instruction: R=0x1, d=1, Z=0. after executing instruction: R=0x0, Z=1, and instruction will skip instruction2 execution because the operation result is zero.

DECR	Decrease R	DISI	Disable Interrupt Globally
Syntax:	DECR R, d	Syntax:	DISI
Operand:	$0 \le R \le 63$	Operand:	
	d = 0, 1.	Operation:	Disable Interrupt, $0 \rightarrow GIE$
Operation:	R - 1 → dest	Status affected:	
Status affected:	Z	Description:	GIE is clear to 0 in order to disable
Description:	Decrease R. If d is 0, the result is	·	all interrupt requests.
	stored in ACC. If d is 1, the result is stored back to R.	Cycle:	1
Cycle:	1	Example:	DISI before executing instruction:
Example:	DECR R, d		GIE=1.
	before executing instruction: R=0x01, d=1, Z=0. after executing instruction: R=0x00, Z=1.		After executing instruction: GIE=0.



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ENI	Enable Interrupt Globally	INCR	NY8AE51D Increase R
Syntax:	ENI	Syntax:	INCR R, d
Operand:		Operand:	$0 \le R \le 63$
Operation:	Enable Interrupt, 1 → GIE		d = 0, 1.
Status affected:		Operation:	$R + 1 \rightarrow dest.$
Description:	GIE is set to 1 in order to enable all	Status affected:	Z
Boompaon.	interrupt requests.	Description:	Increase R. If d is 0, the result is
Cycle:	1		stored in ACC. If d is 1, the result is stored back to R.
Example:	ENI before executing instruction:	Cycle:	1
	GIE=0. After executing instruction: GIE=1.	Example:	INCR R, d before executing instruction: R=0xFF, d=1, Z=0. after executing instruction: R=0x00, Z=1.

GOTOA	Unconditional Branch	INCRSZ	Increase R, Skip if 0
Syntax:	GOTOA	Syntax:	INCRSZ R, d
Operand:		Operand:	$0 \le R \le 63$
Operation:	{TBHP, ACC}→PC		d = 0, 1.
Status affected:		Operation:	$R + 1 \rightarrow dest$ ,
Description:	GOTOA is an unconditional branch		Skip if result = 0
	instruction. The content of TBHP[1:0] is loaded into PC[9:8]	Status affected:	
	and ACC is loaded into PC[7:0].	Description:	Increase R first. If d is 0, the result is stored in ACC. If d is 1, the result
Cycle:	2		is stored back to R.
Example:	GOTOA before executing instruction:		If result is 0, the next instruction which is already fetched is
	PC=A0. TBHP=0x02, ACC=0x34.		discarded and a NOP is executed instead. Therefore it makes this
	after executing instruction: PC=0x234.		instruction a two-cycle instruction.
	1 0-0/204.	Cycle:	1 or 2(skip)
		Example:	INCRSZ R, d instruction2, instruction3.
			before executing instruction: R=0xFF, d=1, Z=0.
			after executing instruction: R=0x00, Z=1. And the program will skip instruction2 execution because the operation result is zero.



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Software Interrupt	IORIA	NY8AE51D OR Immediate with ACC
INT	Syntax:	IORIA i
	Operand:	0 ≤ i < 255
PC + 1 → Top of Stack, 001h → PC	Operation:	ACC   i → ACC
33 III 71 G	Status affected:	Z
Software interrupt. First, return address (PC + 1) is pushed onto	Description:	OR ACC with 8-bit immediate data i. The result is stored in ACC.
the Stack. The address 0x001 is	Cycle:	1
	Example:	IORIA i
3		before executing instruction:
INT before executing instruction: PC=address of INT code. after executing instruction: PC=0x01		i=0x50, ACC=0xAA, Z=0. after executing instruction: ACC=0xFA, Z=0.
	INT   PC + 1 → Top of Stack,  001h → PC   Software interrupt. First, return address (PC + 1) is pushed onto the Stack. The address 0x001 is loaded into PC[9:0].  3  INT  before executing instruction:  PC=address of INT code.	INT Syntax:  Operand:  PC + 1 $\rightarrow$ Top of Stack,  001h $\rightarrow$ PC  Software interrupt. First, return address (PC + 1) is pushed onto the Stack. The address 0x001 is loaded into PC[9:0].  INT  before executing instruction:  PC=address of INT code. after executing instruction:

IORAR	OR ACC with R	
Syntax:	IORAR R, d	
Operand:	0 ≤ R ≤ 63 d = 0, 1.	
Operation:	ACC   R→dest	
Status affected:	Z	
Description:	OR ACC with R. If d is 0, the result is stored in ACC. If d is 1, the result is stored back to R.	
Cycle:	1	
Example:	IORAR R, d before executing instruction: R=0x50, ACC=0xAA, d=1, Z=0. after executing instruction: R=0xFA, ACC=0xAA, Z=0.	

IOST	Load F-page SFR from ACC
Syntax:	IOST F
Operand:	0 ≤ F≤ 15
Operation:	ACC → F-page SFR
Status affected:	
Description:	F-page SFR F is loaded by content of ACC.
Cycle:	1
Example:	IOST F before executing instruction: F=0x55, ACC=0xAA. after executing instruction: F=0xAA, ACC=0xAA.



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IOSTR	Move F-page SFR to ACC	LGOTO	NY8AE51D Unconditional Branch
Syntax:	IOSTR F	Syntax:	LGOTO adr
Operand:	$0 \le F \le 15$	Operand:	$0 \le adr \le 1023$
Operation:	F-page SFR → ACC	Operation:	$adr \rightarrow PC[9:0].$
Status affected:		Status affected:	
Description:	Move F-page SFR F to ACC.	Description:	LGOTO is an unconditional branch
Cycle:	1	·	instruction. The 10-bit immediate address adr is loaded into PC[9:0].
Example:	IOSTR F		• •
	before executing instruction:	Cycle:	2
	F=0x55, ACC=0xAA.  after executing instruction: F=0x55, ACC=0x55.	Example:	LGOTO Level before executing instruction: PC=A0. after executing instruction: PC=address of Level.
			PC=address of Level.

LCALL	Call Subroutine	MOVAR	Move ACC to R
Syntax:	LCALL adr	Syntax:	MOVAR R
Operand:	0 ≤ adr ≤ 1023	Operand:	$0 \le R \le 63$
Operation:	PC + 1 $\rightarrow$ Top of Stack,	Operation:	$ACC \rightarrow R$
	$adr \rightarrow PC[9:0]$	Status affected:	
Status affected:	37 60	Description:	Move content of ACC to R.
Description:	The return address (PC + 1) is	Cycle:	1
	pushed onto top of Stack. The 10-bit immediate address adr is loaded into PC[9:0].	Example:	MOVAR R before executing instruction: R=0x55, ACC=0xAA.
Cycle:	2		after executing instruction:
Example:	LCALL SUB		R=0xAA, ACC=0xAA.
	before executing instruction: PC=A0. Stack level=1 after executing instruction: PC=address of SUB, Stack[1]=		

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A0+1, Stack pointer =2.



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MOVIA	Move Immediate to ACC	NOP	NY8AE51D No Operation
Syntax:	MOVIA i	Syntax:	NOP
Operand:	0 ≤ i < 255	Operand:	
Operation:	$i \rightarrow ACC$	Operation:	No operation.
Status affected:		Status affected:	
Description:	The content of ACC is loaded with	Description:	No operation.
	8-bit immediate data i.	Cycle:	1
Cycle:	1	Example:	NOP
Example:	MOVIA i before executing instruction: i=0x55, ACC=0xAA. after executing instruction: ACC=0x55.		before executing instruction: PC=A0 after executing instruction: PC=A0+1

MOVR	Move to ACC or R	RETIE	Return from Interrupt and Enable Interrupt Globally
Syntax:	MOVR R, d	Syntax:	RETIE
Operand:	$0 \le R \le 63$	Operand:	
Operation:	d = 0, 1. R → dest	Operation:	Top of Stack → PC 1 → GIE
Status affected:	z	Status affected:	<del></del>
Description:	The content of R is move to destination. If d is 0, destination is ACC. If d is 1, destination is R and	Description:	The PC is loaded from top of Stack as return address and GIE is set to 1.
	it can be used to check whether R is zero according to status flag Z	Cycle:	2
	after execution.	Example:	RETIE
Cycle:	1		before executing instruction: GIE=0, Stack level=2.
Example:	MOVR R, d before executing instruction: R=0x0, ACC=0xAA, Z=0, d=0. after executing instruction: R=0x0, ACC=0x00, Z=1.		after executing instruction: GIE=1, PC=Stack[2], Stack level =1.



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RETIA	Return with Data in ACC	RLR	NY8AE51D Rotate Left R Through Carry
Syntax:	RETIA i	Syntax:	RLR R, d
Operand:	0 ≤ i < 255	Operand:	$0 \le R \le 63$ d = 0, 1.
Operation:	i → ACC, Top of Stack → PC	Operation:	$C \rightarrow dest[0], R[7] \rightarrow C,$ $R[6:0] \rightarrow dest[7:1]$
Status affected:			
Description:	ACC is loaded with 8-bit immediate data i and PC is loaded from top of Stack as return address and GIE is set to 1.	C 67	R b6 b5 b4 b3 b2 b1 b0
Cycle:	2	Status affected:	С
Example:	RETIA i before executing instruction: GIE=0, Stack pointer =2, i=0x55, ACC=0xAA.	Description:	The content of R is rotated one bit to the left through flag Carry. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.
	after executing instruction:	Cycle:	
	GIE=1, PC=Stack[2], Stack pointer =1, ACC=0x55.	Example:	RLR R, d before executing instruction: R=0xA5, d=1, C=0. after executing instruction: R=0x4A, C=1

RET	Return from Subroutine
Syntax:	RET
Operand:	
Operation:	Top of Stack → PC
Status affected:	-
Description:	PC is loaded from top of Stack as return address.
Cycle:	2
Example:	RET before executing instruction: Stack level=2.

after executing instruction: PC=Stack[2], Stack level=1.

RRR	Rotate Right R Through Carry			
Syntax:	RRR R, d			
Operand:	$0 \le R \le 63$ d = 0, 1.			
Operation:	$C \rightarrow dest[7], R[7:1] \rightarrow dest[6:0], R[0] \rightarrow C$			
C	R			
b)	7   b6   b5   b4   b3   b2   b1   b0			

	_					•				
	•	b7	b6	b5	b4	b3	b2	b1	b0	
Status affection		d:	C The	con	tent	of R	is ro	otateo	d one	e bit
·			is 0	, the	ght ti resu he re	ılt is	plac	ed in	ΑĆ	C. If
Cycle:			1							

Example:

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RRR R, d before executing instruction:	
R=0xA5, d=1, C=0. after executing instruction: R=0x52, C=1.	



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		NY8AE51D
	SBCIA	Subtract ACC and Carry from Immediate
,	Syntax:	SBCIA i
$0 \le R \le 63$ d = 0, 1.	Operand:	0 ≤ i < 255
$R + (\sim ACC) + C \rightarrow dest$	Operation:	$i + (\sim ACC) + C \rightarrow dest$
,	Status affected:	Z, DC, C
Subtract ACC and Carry from R with 2's complement representation. If d is 0, the result is placed in ACC. If d is 1, the	Description:	Subtract ACC and Carry from 8-bit immediate data i with 2's complement representation. The result is placed in ACC.
result is stored back to R.	Cycle:	1
1	Example:	SBCIA i
SBCAR R, d  (a) before executing instruction:  R=0x05, ACC=0x06, d=1, C=0.  after executing instruction:  R=0xFE, C=0. (-2)  (b) before executing instruction:  R=0x05, ACC=0x06, d=1, C=1.  after executing instruction:  R=0xFF, C=0. (-1)  (c) before executing instruction:  R=0x06, ACC=0x05, d=1, C=0.  after executing instruction:  R=0x00, C=1. (-0), Z=1.  (d) before executing instruction:  R=0x06, ACC=0x05, d=1, C=1.  after executing instruction:  R=0x06, ACC=0x05, d=1, C=1.		<ul> <li>(a) before executing instruction: i=0x05, ACC=0x06, C=0. after executing instruction: ACC=0xFE, C=0. (-2)</li> <li>(b) before executing instruction: i=0x05, ACC=0x06, C=1. after executing instruction: ACC=0xFF, C=0. (-1)</li> <li>(c) before executing instruction: i=0x06, ACC=0x05, C=0. after executing instruction: ACC=0x00, C=1. (-0), Z=1.</li> <li>(d) before executing instruction: i=0x06, ACC=0x05, C=1. after executing instruction: ACC=0x1, C=1. (+1)</li> </ul>
	R + (~ACC) + C → dest  Z, DC, C  Subtract ACC and Carry from R with 2's complement representation. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.  1  SBCAR R, d  (a) before executing instruction: R=0x05, ACC=0x06, d=1, C=0. after executing instruction: R=0xFE, C=0. (-2)  (b) before executing instruction: R=0x05, ACC=0x06, d=1, C=1. after executing instruction: R=0xFF, C=0. (-1)  (c) before executing instruction: R=0xFF, C=0. (-1)  (d) before executing instruction: R=0x00, C=1. (-0), Z=1.  (d) before executing instruction: R=0x06, ACC=0x05, d=1, C=1.	SBCAR R, d $0 \le R \le 63$ $d = 0, 1.$ $R + (\sim ACC) + C \rightarrow dest$ $Z, DC, C$ Subtract ACC and Carry from R with 2's complement representation. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.  1  SBCAR R, d  (a) before executing instruction: $R = 0x05, ACC = 0x06, d = 1, C = 0.$ after executing instruction: $R = 0x05, ACC = 0x06, d = 1, C = 1.$ after executing instruction: $R = 0x05, ACC = 0x06, d = 1, C = 1.$ after executing instruction: $R = 0x05, ACC = 0x06, d = 1, C = 1.$ after executing instruction: $R = 0x06, ACC = 0x05, d = 1, C = 0.$ after executing instruction: $R = 0x00, C = 1. (-0), Z = 1.$ (d) before executing instruction: $R = 0x06, ACC = 0x05, d = 1, C = 1.$ after executing instruction: $R = 0x06, ACC = 0x05, d = 1, C = 1.$ after executing instruction: $R = 0x06, ACC = 0x05, d = 1, C = 1.$ after executing instruction:



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SFUN	Load S-page SFR from ACC		NY8AE51D
Syntax:	SFUN S	SLEEP	Enter Halt Mode
Operand:	$0 \le S \le 15$	Syntax:	SLEEP
Operation:	ACC → S-page SFR	Operand:	
Status affected: Description:	S-page SFR S is loaded by content of ACC.	Operation:	00h → WDT, 00h → WDT prescaler 1 → /TO 0 → /PD
Cycle:	1	Status affected:	/TO, /PD
Example:	SFUN S before executing instruction: S=0x55, ACC=0xAA. after executing instruction: S=0xAA, ACC=0xAA.	Description:	WDT and Prescaler0 are clear to 0. /TO is set to 1 and /PD is clear to 0. IC enter Halt mode.
	3-000-000	Cycle:	1
		Example:	SLEEP before executing instruction: /PD=1, /TO=0.

SFUNR	Move S-page SFR to ACC	SUBAR	Subtract ACC from R
Syntax:	SFUNR S	Syntax:	SUBAR R, d
Operand:	0 ≤ S ≤ 15	Operand:	$0 \le R \le 63$ d = 0, 1.
Operation: Status affected:	S-page SFR → ACC  Move S-page SFR S to ACC.  SFUNR S before executing instruction: S=0x55, ACC=0xAA. after executing instruction: S=0x55, ACC=0x55.	Operation: Status affected:	$R - ACC \rightarrow dest$ Z, DC, C
Description: Cycle: Example:		Description:	Subtract ACC from R with 2's complement representation. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.
		Cycle: Example:	1 SBCAR R, d
			(a) before executing instruction: R=0x05, ACC=0x06, d=1. after executing instruction: R=0xFF, C=0. (-1)
			(b) before executing instruction: R=0x06, ACC=0x05, d=1. after executing instruction: R=0x01, C=1. (+1)

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after executing instruction:

/PD=0, /TO=1.



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CUDIA	Outstand A O O from large distant	TABLEA	NY8AE51D Read ROM data
SUBIA	Subtract ACC from Immediate	Syntax:	TABLEA
Syntax:	SUBIA i	Operand:	
Operand:	0 ≤ i < 255	o por amar	
Operation:	$i-ACC \rightarrow ACC$	Operation:	ROM data{ TBHP, ACC } [7:0] → ACC
Status affected:	Z, DC, C		ROM data{TBHP, ACC} [13:8]
Description:	Subtract ACC from 8-bit immediate		$\rightarrow$ TBHD.
	data i with 2's complement representation. The result is placed	Status affected:	
	in ACC.	Description:	The 8 least significant bits of ROM
Cycle:	1		pointed by {TBHP[2:0], ACC} is placed to ACC.
Example:	SUBIA i		The 6 most significant bits of ROM
	(a) before executing instruction:		pointed by {TBHP[2:0], ACC} is placed to TBHD[5:0].
	i=0x05, ACC=0x06.		
	after executing instruction:	Cycle:	2
	ACC=0xFF, C=0. (-1)	Example:	TABLEA
	(b) before executing instruction: i=0x06, ACC=0x05, d=1. after executing instruction: ACC=0x01, C=1. (+1)		before executing instruction: TBHP=0x02, CC=0x34. TBHD=0x01. ROM data[0x234]= 0x35AA
			after executing instruction: TBHD=0x35, ACC=0xAA.

SWAPR	Swap High/Low Nibble in R
Syntax:	SWAPR R, d
Operand:	$0 \le R \le 63$ d = 0, 1.
Operation:	$R[3:0] \rightarrow dest[7:4].$ $R[7:4] \rightarrow dest[3:0]$
Status affected:	<b>101</b> P
Description:	The high nibble and low nibble of R is exchanged. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	SWAPR R, d before executing instruction: R=0xA5, d=1. after executing instruction: R=0x5A.

TOMD	Load ACC to T0MD
Syntax:	TOMD
Operand:	
Operation:	ACC→ T0MD
Status affected:	
Description:	The content of T0MD is loaded by ACC.
Cycle:	1
Example:	TOMD before executing instruction:   T0MD=0x55, ACC=0xAA. after executing instruction:   T0MD=0xAA.



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T0MDR	Move T0MD to ACC	XORIA	Exclusive-OR Immediate with ACC
Syntax:	T0MDR	Syntax:	XORIA i
Operand:		Operand:	0 ≤ i < 255
Operation:	$TOMD \rightarrow ACC$	·	
Status affected:		Operation:	$ACC \oplus i \rightarrow ACC$
	Move the content of T0MD to ACC.	Status affected:	Z
Description: Move the content of T0MI  Cycle: 1  Example: T0MDR	1 T0MDR	Description:	Exclusive-OR ACC with 8-bit immediate data i. The result is stored in ACC.
	before executing instruction T0MD=0x55, ACC=0xAA.	Cycle:	1
	after executing instruction ACC=0x55.	Example:	XORIA i before executing instruction: i=0xA5, ACC=0xF0. after executing instruction: ACC=0x55.

XORAR	Exclusive-OR ACC with R
Syntax:	XORAR R, d
Operand:	$0 \le R \le 63$ d = 0, 1.
Operation:	$ACC \oplus R \rightarrow dest$
Status affected:	Z
Description:	Exclusive-OR ACC with R. If d is 0, the result is placed in ACC. If d is 1, the result is stored back to R.
Cycle:	1
Example:	XORAR R, d before executing instruction: R=0xA5, ACC=0xF0, d=1. after executing instruction: R=0x55.



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### 5. Configuration Words

Item	Name	Options
1	High IRC Frequency	1. 1MHz 2. 2MHz 3. 4MHz
'	riigiriiko rrequency	4. 8MHz 5. 16MHz 6. 20MHz
2	Instruction Clock	2. 4 oscillator period     2. 4 oscillator period
3	WDT	Watchdog Enable (Software control)
		Watchdog Disable (Always disable)
4	WDT Event	Watchdog Reset     Z. Watchdog Interrupt
5	Timer0 source	1. EX_CKI 2. I_LRC
6	PB.2	1. PB.2 is I/O 2. PB.2 is PWM 3. PB.2 is Buzzer
7	PB.3	1. PB.3 is I/O 2. PB.3 is reset
8	PB.4	PB.4 is I/O     PB.4 is instruction clock output
9	Startup Time	1. 140us 2. 4.5ms 3. 18ms 4. 72ms 5. 288ms
10	WDT Time Base	1. 3.5ms 2. 15ms 3. 60ms 4. 250ms
11	LVR Setting	Register Control     Register Control + Halt mode Off
	LVIX Octains	3. Always On 4. Operation mode On + Halt mode Off
12	LVR Voltage	1. 1.6V 2. 1.8V 3. 2.0V 4. 2.2V 5. 2.4V
	ZVIV vollage	6. 2.7V 7. 3.0V 8. 3.3V 9. 3.6V 10. 4.2V
13	VDD Voltage	1. 3.0V 2. 4.5V 3. 5.0V
14	Read Output Data	1. I/O port 2. Register
15	EX_CKI to Inst. Clock	1. Sync 2. Async
16	Startup Clock	1. I_HRC 2. I_LRC
17	Input High Voltage (VIH)	1. CMOS (0.7VDD) 2. TTL (0.5VDD)
18	Input Low Voltage (VIL)	1. CMOS (0.3VDD) 2. TTL (0.2VDD)
19	Input Voltage Schmitt Trigger	1. Enable (depend on 17, 18) 2. Disable (17, 18 no use)
20	Sink / Drive Current	1. Small 2. Normal

Table 15 Configuration Words



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#### 6. Electrical Characteristics

#### 6.1 Absolute Maximum Rating

Symbol	Parameter	Parameter Rated Value			
$V_{DD}$ - $V_{SS}$	Supply voltage	-0.5 ~ +6.0	V		
$V_{IN}$	Input voltage	V <sub>SS</sub> -0.3V ~ V <sub>DD</sub> +0.3	V		
T <sub>OP</sub>	Operating Temperature	-40 ~ +85	°C		
T <sub>ST</sub>	Storage Temperature	-40 ~ +125	°C		

#### 6.2 DC Characteristics

(All refer  $F_{INST}$ = $F_{HOSC}$ /4,  $F_{HOSC}$ =16MHz@I\_HRC, WDT enabled, ambient temperature  $T_A$ =25°C unless otherwise specified.)

Symbo	Parameter	V <sub>DD</sub>	Min.	Тур.	Max.	Unit	Condition
			3.0				F <sub>INST</sub> =20MHz @ I_HRC/2
			2.0			くろ	F <sub>INST</sub> =20MHz @ I_HRC/4
			2.7				F <sub>INST</sub> =16MHz @ I_HRC/2
			2.0				F <sub>INST</sub> =16MHz @ I_HRC/4
$V_{DD}$	Operating voltage		1.6		5.5	V	F <sub>INST</sub> =8MHz @ I_HRC/4
			1.6				F <sub>INST</sub> =4MHz @ I_HRC/4
			1.6				F <sub>INST</sub> =2MHz @ I_HRC/4
			1.6				F <sub>INST</sub> =1MHz @ I_HRC/4
			1.6				F <sub>INST</sub> =32KHz @ I_LRC/4 & I_LRC/2
		5V	4.0			V	RSTb (0.8V <sub>DD</sub> )
		3V	2.4		-	V	K310 (0.6V <sub>DD</sub> )
	$\Lambda \lambda I$	5V	3.5			٧	All other I/O pins, EX_CKI, INT
	Input high voltage	3V	2.1	\ <u>-</u> -	<b>/</b>	V	CMOS (0.7V <sub>DD</sub> )
$V_{IH}$		5V	2.5			V	All other I/O pins, EX_CKI, INT
		3V	1.5			\ \	TTL (0.5V <sub>DD</sub> )
	1011	5V	2.0			V	All other I/O pins, EX_CKI, INT
		3V	1.2			V	No Schmitt Trigger (0.4 <sub>VDD</sub> )
		5V			1.0	V	RSTb (0.2V <sub>DD</sub> )
		3V			0.6	V	K310 (0.2V <sub>DD</sub> )
		5V			1.5	V	All other I/O pins, EX_CKI, INT
$V_{IL}$	Input low voltage	3V			0.9	v	CMOS (0.3V <sub>DD</sub> )
V IL	iliput low voltage	5V			1.0	V	All other I/O pins, EX_CKI, INT
		3V			0.6	V	TTL (0.2V <sub>DD</sub> )
		5V			2.0	V	All other I/O pins, EX_CKI, INT
		3V			1.2	v	No Schmitt Trigger (0.4 <sub>VDD</sub> )
	Small Drive Current	5V		-2		mA	V <sub>OH</sub> =4.0V
la	Small Drive Current	3V		-1		111/	V <sub>OH</sub> =2.0V
I <sub>OH</sub>	Normal Drive	5V		-18		mA	V <sub>OH</sub> =4.0V
	Current	3V		-10		IIIA	V <sub>OH</sub> =2.0V
$I_{OL}$	Small Sink Current	5V		10		mA	V <sub>OL</sub> =1.0V







Symbo	NY8AE51D							
I	Parameter	V <sub>DD</sub>	Min.	Тур.	Max.	Unit	Condition	
		3V		5				
	Normal Sink	5V		43		m A	\/ -1.0\/	
	Current	3V		25		mA	V <sub>OL</sub> =1.0V	
	ID sink surrent	5V		43		A	\/ -4.0\/ Normal ID	
I <sub>IR</sub>	IR sink current	3V		25		mA	V <sub>OL</sub> =1.0V, Normal IR	
						No	rmal Mode	
		5V		5.4		mA	E -20MH-2 @ 1 HBC/2	
		3V		3.2		IIIA	F <sub>HOSC</sub> =20MHz @ I_HRC/2	
		5V		4.0		mA	F <sub>HOSC</sub> =20MHz @ I_HRC/4	
		3V		2.8		IIIA	1 HOSC=20WI12 @ 1_111(0/4	
		5V		4.7		mA	F <sub>HOSC</sub> =16MHz @ I_HRC/2	
		3V		2.9		IIIA	PHOSC - TOWN 12 @ 1_11RC/2	
		5V		3.7		mΛ	E -16MU-7 @ L UDC/4	
		3V		2.6	- 4	mA	F <sub>HOSC</sub> =16MHz @ I_HRC/4	
		5V		2.6		mA	F <sub>HOSC</sub> =8MHz @ I_HRC/2	
		3V		2.0	4	IIIA	PHOSC-OWITZ @ 1_1TKC/2	
	I <sub>OP</sub> Operating current	5V		1.8	, \	mΛ	F <sub>HOSC</sub> =8MHz @ I_HRC/4	
		3V	-	1.3	-	mA	PHOSC-OWINZ @ I_NC/4	
IOP		5V		1.8		mA	F <sub>HOSC</sub> =4MHz @ I_HRC/2	
		3V		1.3			PHOSC-4WITZ @ I_TINO/2	
		5V	-	1.3		mA	F <sub>HOSC</sub> =4MHz @ I_HRC/4	
		3V		0.9		IIIA	Hosc=4Wil12 @ I_I IIXO/4	
		5V		1.0		mΛ	F <sub>HOSC</sub> =1MHz @ I_HRC/2	
	$\mathcal{K} \mathcal{M} \mathcal{M}$	3V	1	0.7	1	mA	PHOSC - HVII IZ @ I_HKC/Z	
		5V		0.8	<b>)</b>	mA		
		3V		0.5		IIIA	F <sub>HOSC</sub> =1MHz @ I_HRC/4	
		Slow mode						
	1011	5V		16.6		uA	F <sub>HOSC</sub> disabled,	
		3V		13.9		uA	F <sub>LOSC</sub> =32KHz @ I_LRC/2	
		5V		9.7		uA	F <sub>HOSC</sub> disabled,	
		3V		7.3		uA	F <sub>LOSC</sub> =32KHz @ I_LRC/4	
1	Standby current	5V		3.0		uA	Standby mode, F <sub>HOSC</sub> disabled,	
I <sub>STB</sub>	- Standby current	3V		1.0		uA	F <sub>LOSC</sub> =32KHz @ I_LRC/4	
		5V			0.5	uA	Halt mode, WDT disabled.	
I <sub>HALT</sub>	Halt current	3V			0.2	u/\	Tidit mode, WDT disabled.	
	Tidit Guirellt	5V			5	uA	Halt mode, WDT enabled.	
		3V			2	uA	Hait mode, WDT chapied.	
R <sub>PH</sub>	Pull-High resistor	5V		60		kΩ	Pull-High resistor	
' YPH	. an ingritosistor	3V		120		17.5.2	1 dii 1 ligii 1 ddioloi	
R <sub>PL</sub>	Pull-Low resistor	5V		55		kΩ	Ω Pull-Low resistor	
1 YPL	. dii Low rosisioi	3V		105		1/77	1 4.1 2011 10010101	



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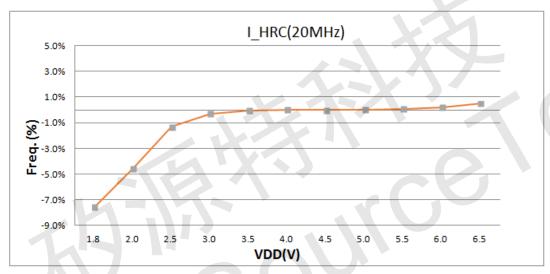
#### **OSC Characteristics** 6.3

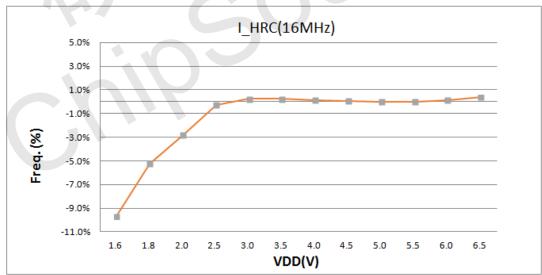
(Measurement conditions  $V_{\text{DD}}$  Voltage,  $T_{\text{A}}$  Temperature are equal to programming conditions.)

Parameter	Min.	Тур.	Max.	Unit	Condition
I_HRC deviation by socket			±1	%	Socket installed directly on writer.
I_HRC deviation by handler			±3	%	Handler condition with correct setup.
I_LRC deviation by handler			±5	%	

#### 6.4 Characteristic Graph

### Frequency vs. V<sub>DD</sub> of I\_HRC





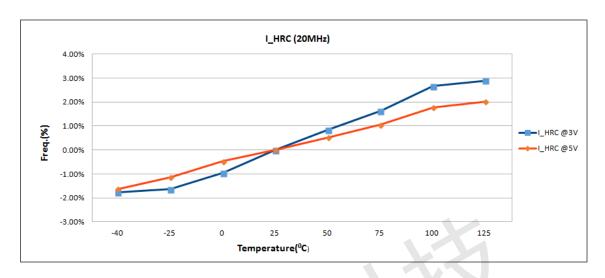


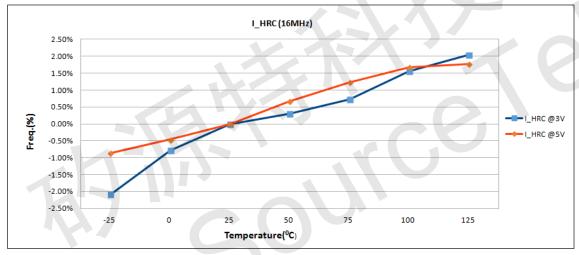
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### 6.4.2 Frequency vs. Temperature of I\_HRC





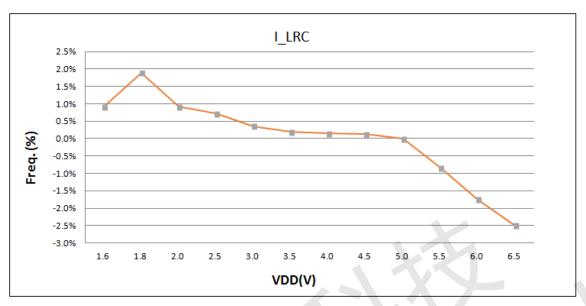


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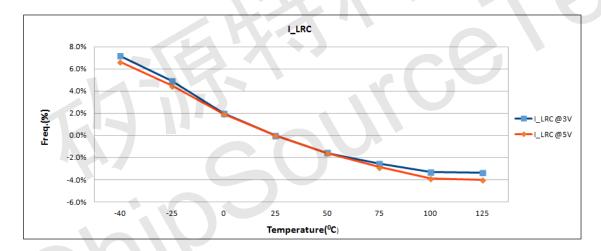


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### 6.4.3 Frequency vs. $V_{DD}$ of I\_LRC



### 6.4.4 Frequency vs. Temperature of I\_LRC

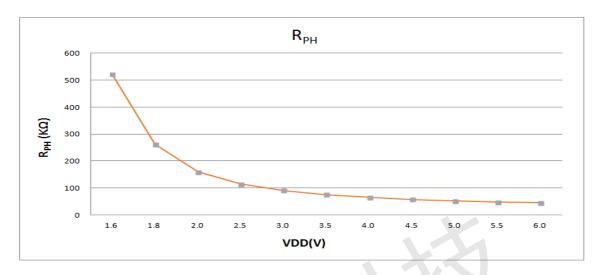




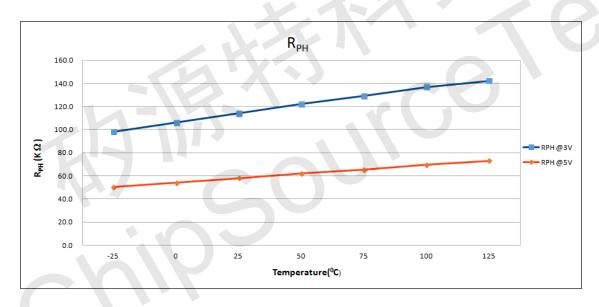


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#### 6.4.5 Pull High Resistor vs. VDD



### 6.4.6 Pull High Resistor vs. Temperature

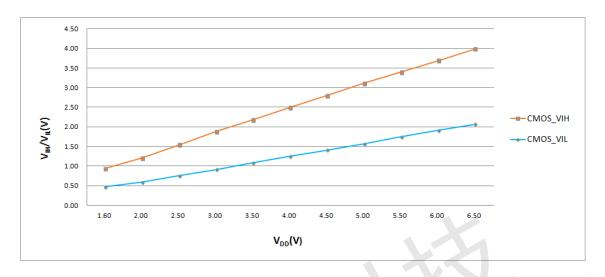


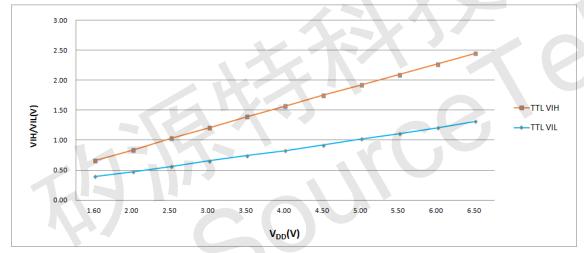
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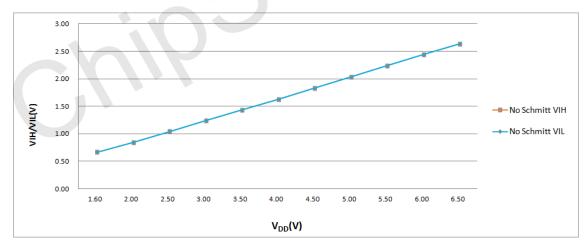


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#### 6.4.7 VIH/VIL vs. VDD





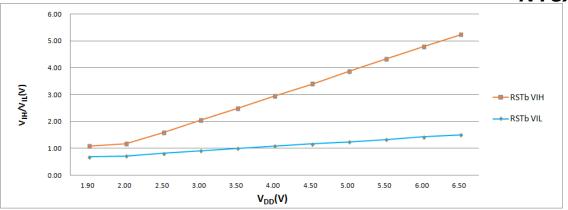




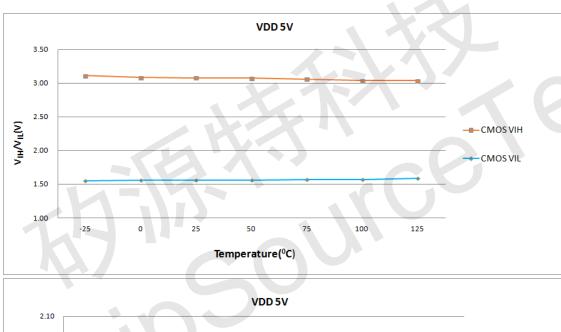
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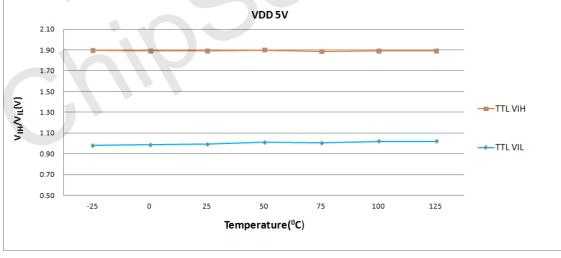






#### 6.4.8 VIH/VIL vs. Temperature



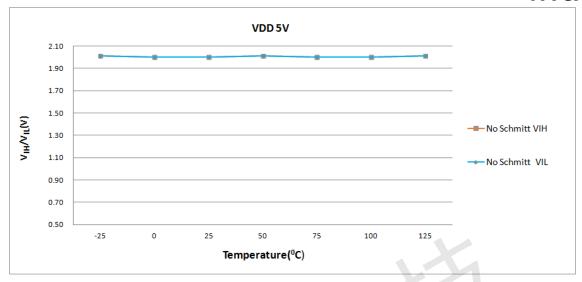


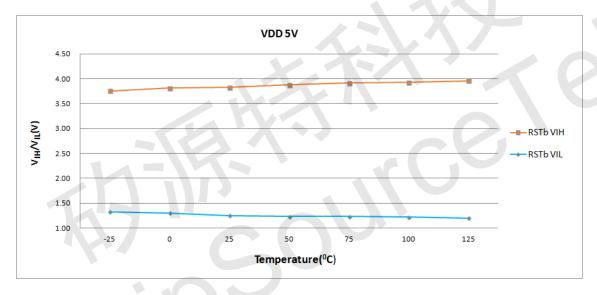


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### **Recommended Operating Voltage**

Recommended Operating Voltage (Temperature range: -40 °C ~ +85 °C)

Frequency	Min. Voltage	Max. Voltage	LVR : default ( 25 °C)	LVR : Recommended (-40 °C ~ +85 °C)
20M/2T	3.0V	5.5V	3.0V	3.3V
16M/2T	2.7V	5.5V	2.7V	3.0V
20M/4T	2.0V	5.5V	2.4V	2.4V
16M/4T or 8M/2T	2.0V	5.5V	2.4V	2.4V
8M/4T or 4M/2T	1.6V	5.5V	2.4V	2.4V
4M/4T or 2M/2T	1.6V	5.5V	2.4V	2.4V
2M/4T or 1M/2T	1.6V	5.5V	2.4V	2.4V
1M/4T	1.6V	5.5V	2.4V	2.4V

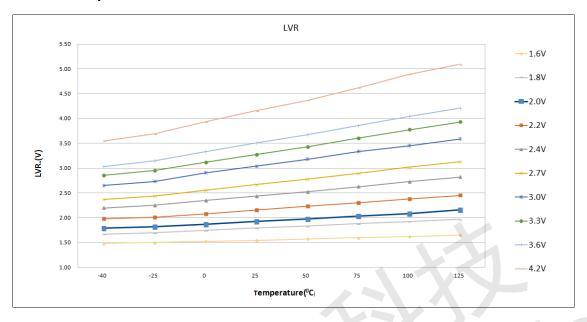


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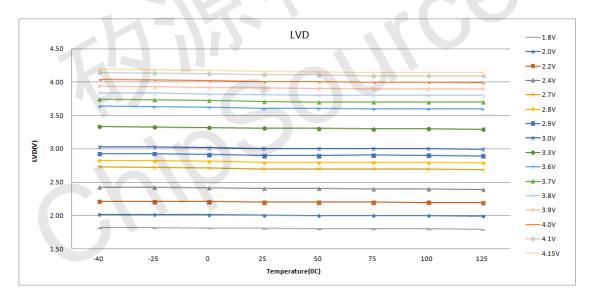


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#### 6.6 LVR vs. Temperature



#### 6.7 LVD vs. Temperature



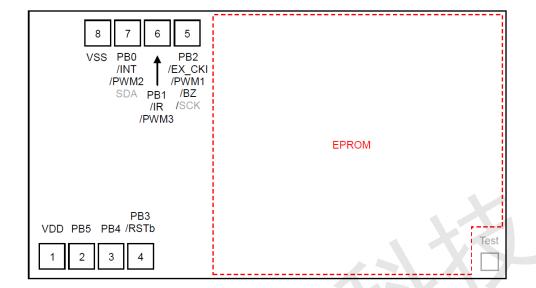


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### 7. Die Pad Diagram





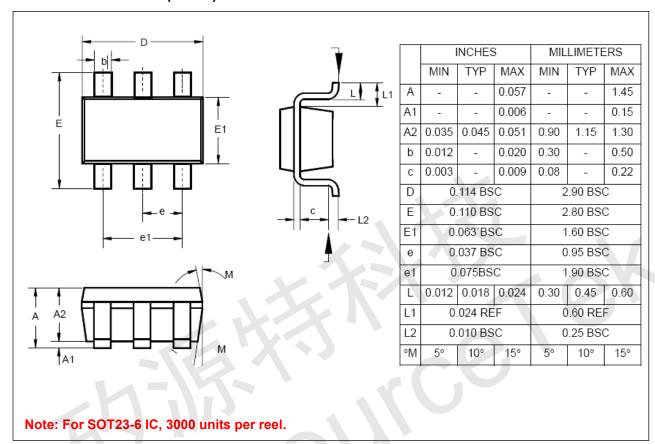
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NY8AE51D

#### Package Dimension

#### 8.1 6-Pin Plastic SOT23-6 (63 mil)



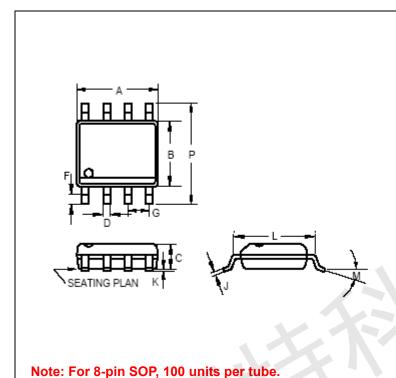


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#### 8.2 8-Pin Plastic SOP (150 mil)



	_	NCHES	Š	MILLIMETERS			
	MIN	TYP	MAX	MIN	TYP	MAX	
А	0.183	-	0.202	4.65	-	5.13	
В	0.144	,	0.163	3.66	,	4.14	
С	0.068	-	0.074	1.35	1	1.88	
D	0.010	-	0.020	0.25	-	0.51	
F	0.015	-	0.035	0.38	-	0.89	
G	0.	050 BS	iC .	1.27 BSC			
5	0.007	1	0.010	0.19	,	0.25	
к	0.005	Ţ.	0.010	0.13	-	0.25	
L	0.189	-	0.205	4.80	-	5.21	
М	-	-	80	-		8°	
Р	0.228	-	0.244	5.79		6.20	

### 9. Ordering Information

P/N	Package Type	Pin Count	Package Width	Shipping
NY8AE51D	Die		-	1
NY8AE51DS6	SOT23-6	6	63 mil	Tape & Reel: 3.0K pcs per Reel
NY8AE51DS8	SOP	8	150 mil	Tape & Reel: 2.5K pcs per Reel  Tube: 100 pcs per Tube

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TEL: +86-0755-27595155 27595165 FAX: +86-0755-27594792 WEB:Http://www.ChipSourceTek.com E-mail: Sales@ChipSourceTek.com Tony.Wang@ChipSourceTek.com